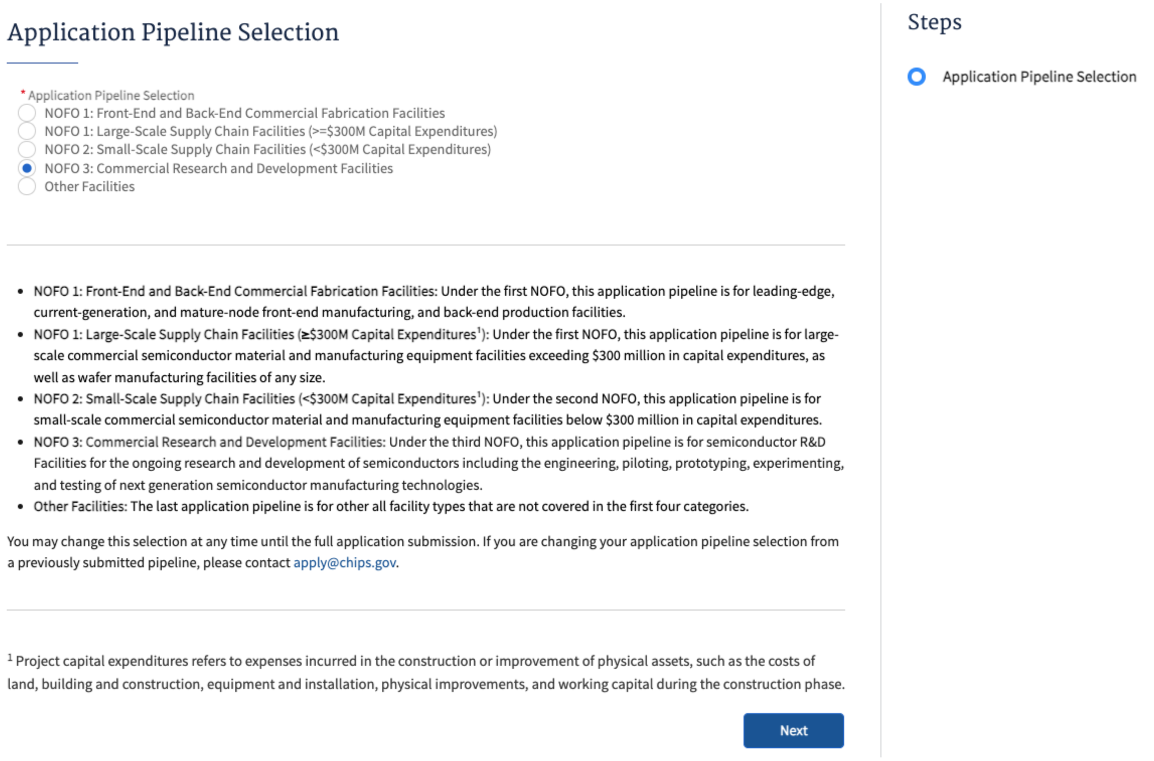
NOFO3 Concept Plan & Full Application - PRA Screenshots

NOFO3 Concept Plan

Application Pipeline Selection



Application Pipeline Selection

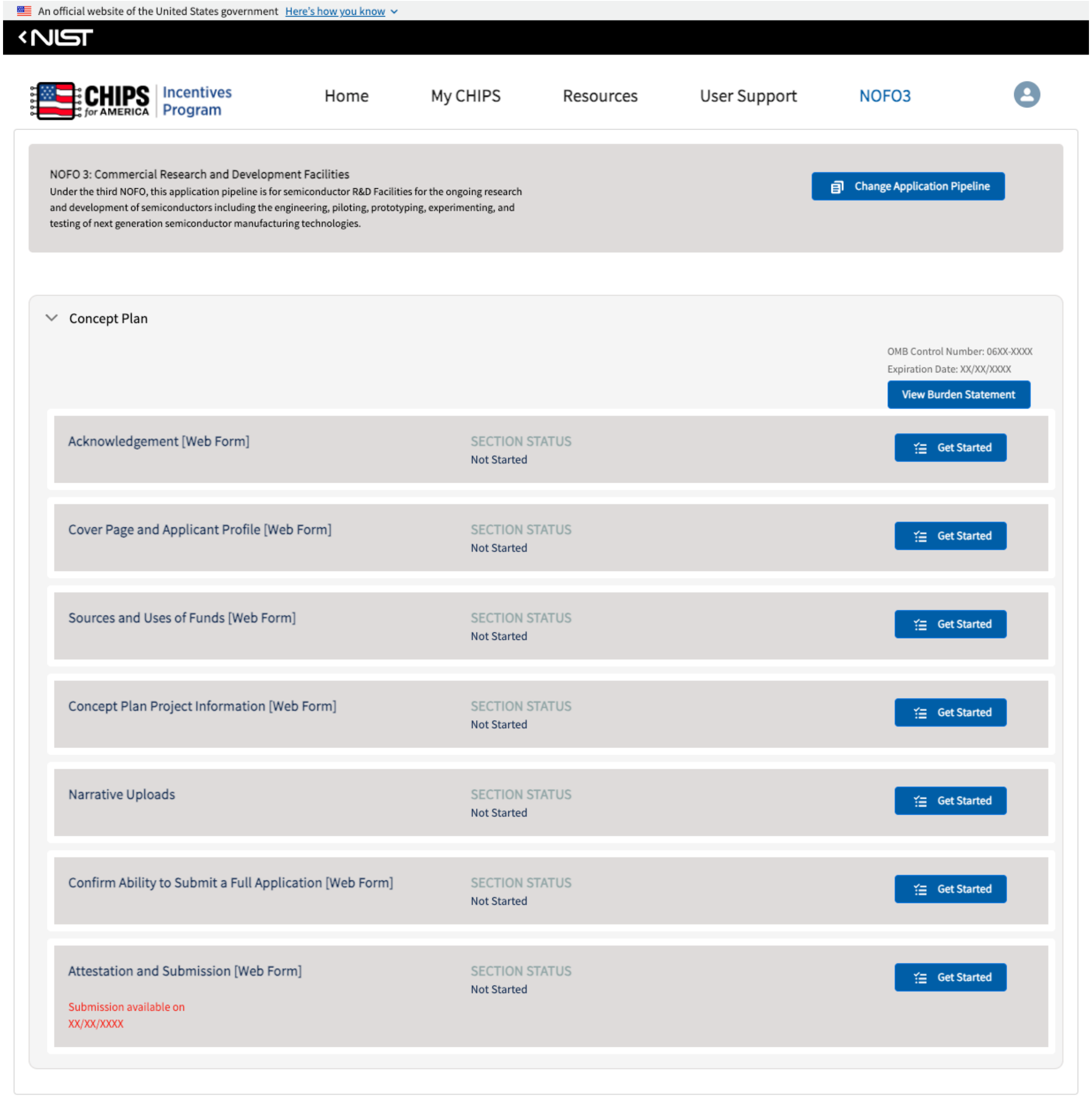
* Application Pipeline Selection
○ NOFO 1: Front-End and Back-End Commercial Fabrication Facilities
○ NOFO 1: Large-Scale Supply Chain Facilities (>=$300M Capital Expenditures)
○ NOFO 2: Small-Scale Supply Chain Facilities (<$300M Capital Expenditures)
● NOFO 3: Commercial Research and Development Facilities
○ Other Facilities

- NOFO 1: Front-End and Back-End Commercial Fabrication Facilities: Under the first NOFO, this application pipeline is for leading-edge, current-generation, and mature-node front-end manufacturing, and back-end production facilities.
- NOFO 1: Large-Scale Supply Chain Facilities (≥$300M Capital Expenditures[1]): Under the first NOFO, this application pipeline is for large-scale commercial semiconductor material and manufacturing equipment facilities exceeding $300 million in capital expenditures, as well as wafer manufacturing facilities of any size.
- NOFO 2: Small-Scale Supply Chain Facilities (<$300M Capital Expenditures[1]): Under the second NOFO, this application pipeline is for small-scale commercial semiconductor material and manufacturing equipment facilities below $300 million in capital expenditures.
- NOFO 3: Commercial Research and Development Facilities: Under the third NOFO, this application pipeline is for semiconductor R&D Facilities for the ongoing research and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.
- Other Facilities: The last application pipeline is for other all facility types that are not covered in the first four categories.

You may change this selection at any time until the full application submission. If you are changing your application pipeline selection from a previously submitted pipeline, please contact apply@chips.gov.

[1] Project capital expenditures refers to expenses incurred in the construction or improvement of physical assets, such as the costs of land, building and construction, equipment and installation, physical improvements, and working capital during the construction phase.

Landing Page



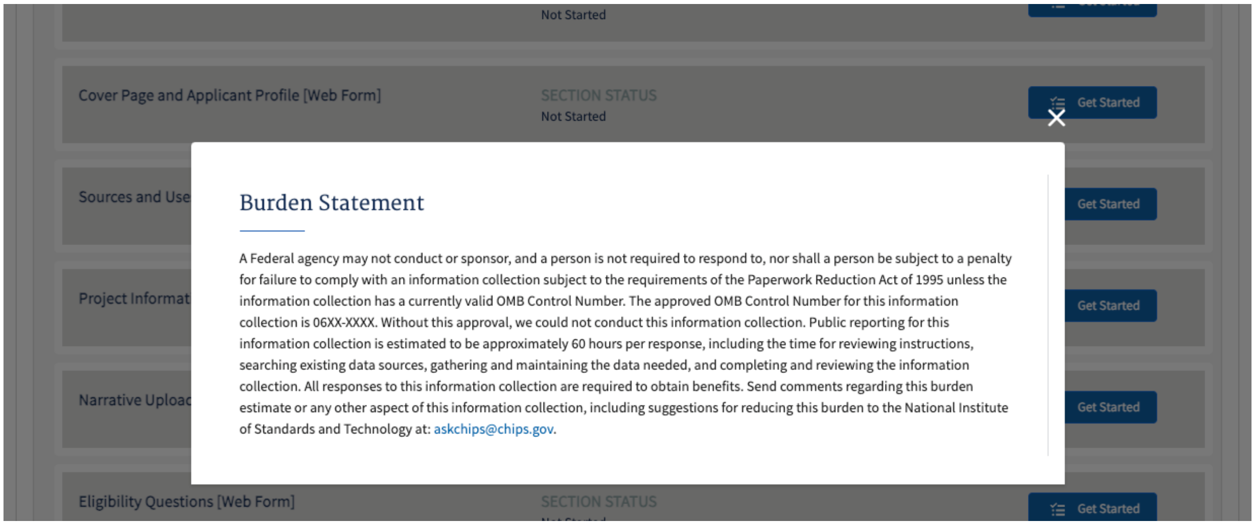
NOFO 3: Commercial Research and Development Facilities

Under the third NOFO, this application pipeline is for semiconductor R&D Facilities for the ongoing research and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.

OMB Control Number: 06XX-XXXX
Expiration Date: XX/XX/XXXX

	SECTION STATUS	
Acknowledgement [Web Form]	Not Started	Get Started
Cover Page and Applicant Profile [Web Form]	Not Started	Get Started
Sources and Uses of Funds [Web Form]	Not Started	Get Started
Concept Plan Project Information [Web Form]	Not Started	Get Started
Narrative Uploads	Not Started	Get Started
Confirm Ability to Submit a Full Application [Web Form]	Not Started	Get Started
Attestation and Submission [Web Form] Submission available on XX/XX/XXXX	Not Started	Get Started

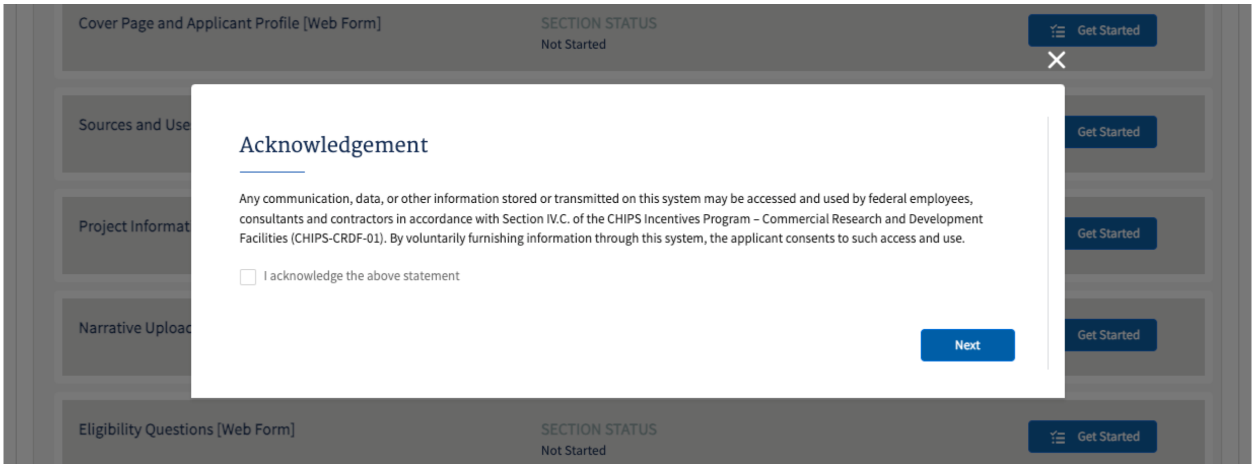
Burden Statement



Burden Statement

A Federal agency may not conduct or sponsor, and a person is not required to respond to, nor shall a person be subject to a penalty for failure to comply with an information collection subject to the requirements of the Paperwork Reduction Act of 1995 unless the information collection has a currently valid OMB Control Number. The approved OMB Control Number for this information collection is 06XX-XXXX. Without this approval, we could not conduct this information collection. Public reporting for this information collection is estimated to be approximately 60 hours per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the information collection. All responses to this information collection are required to obtain benefits. Send comments regarding this burden estimate or any other aspect of this information collection, including suggestions for reducing this burden to the National Institute of Standards and Technology at: askchips@chips.gov.

Acknowledgment Statement



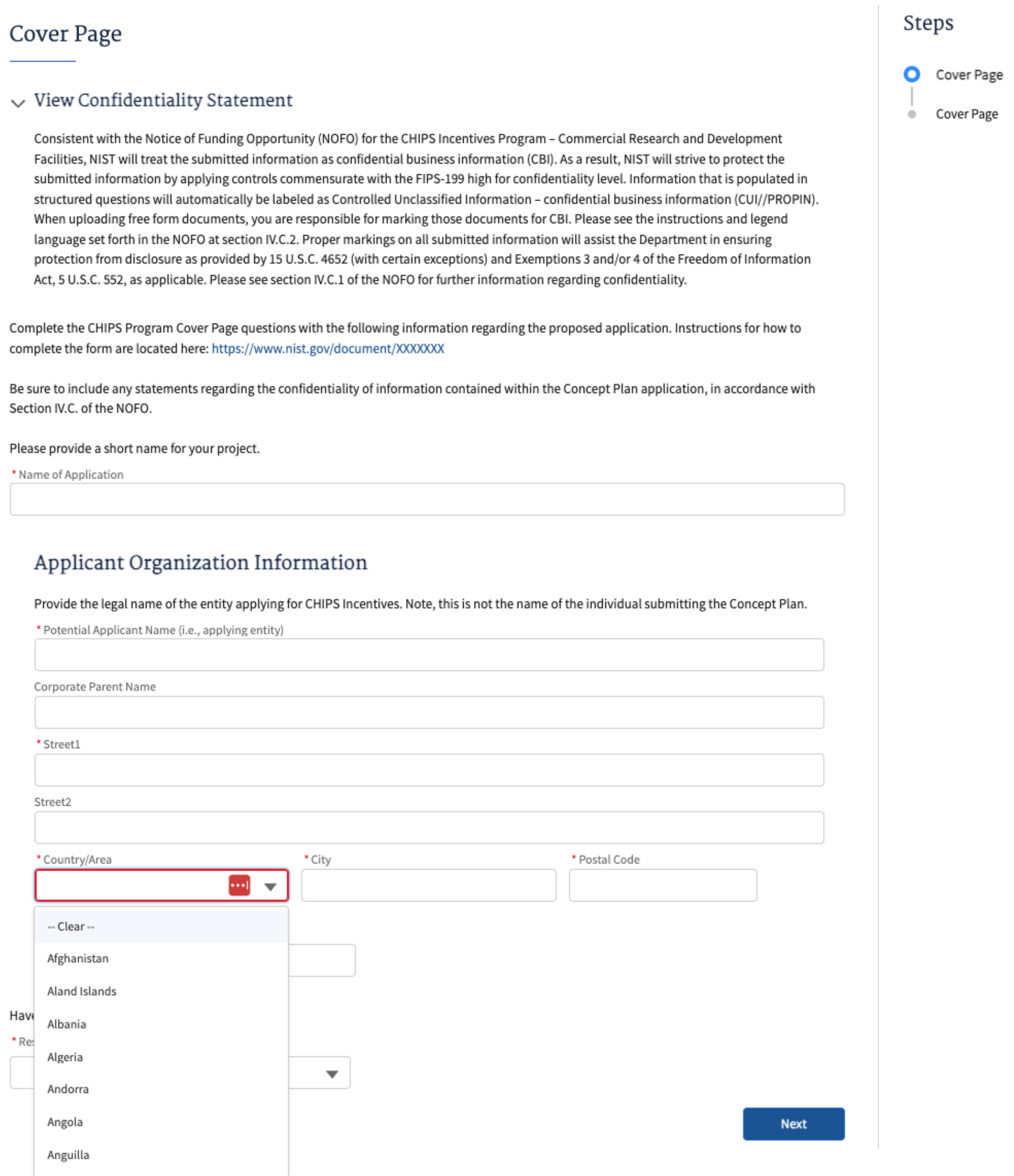
Acknowledgement

Any communication, data, or other information stored or transmitted on this system may be accessed and used by federal employees, consultants and contractors in accordance with Section IV.C. of the CHIPS Incentives Program – Commercial Research and Development Facilities (CHIPS-CRDF-01). By voluntarily furnishing information through this system, the applicant consents to such access and use.

☐ I acknowledge the above statement

Cover Page and Applicant Profile [Web Form]

Application Organization Information



Cover Page

View Confidentiality Statement

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Commercial Research and Development Facilities, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

Complete the CHIPS Program Cover Page questions with the following information regarding the proposed application. Instructions for how to complete the form are located here: https://www.nist.gov/document/XXXXXXX

Be sure to include any statements regarding the confidentiality of information contained within the Concept Plan application, in accordance with Section IV.C. of the NOFO.

Please provide a short name for your project.

* Name of Application

Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Concept Plan.

* Potential Applicant Name (i.e., applying entity)

Corporate Parent Name

* Street1

Street2

* Country/Area

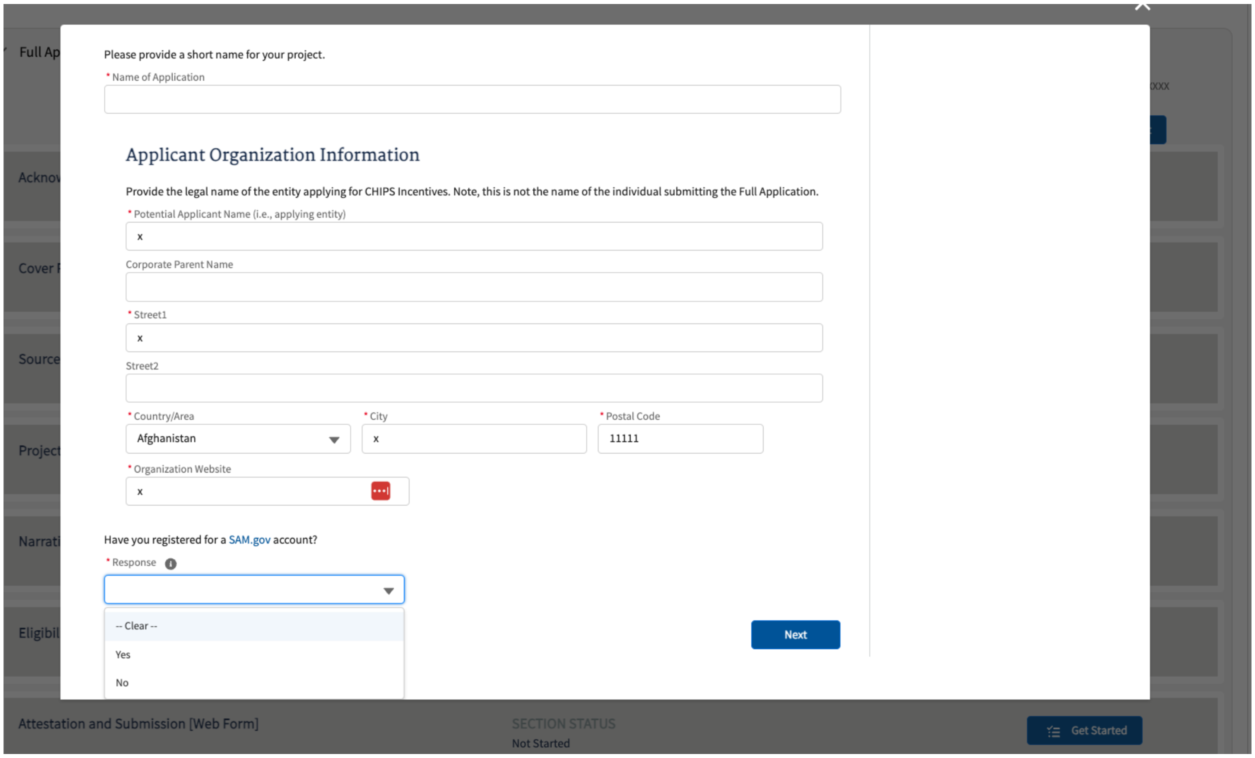
* City

* Postal Code

Hav

* Re

Picklist: Country/Area
Picklist Values: Standard list of Countries



Please provide a short name for your project.

* Name of Application

Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Full Application.

* Potential Applicant Name (i.e., applying entity): x

Corporate Parent Name

* Street1: x

Street2

* Country/Area: Afghanistan

* City: x

* Postal Code: 11111

* Organization Website: x

Have you registered for a SAM.gov account?

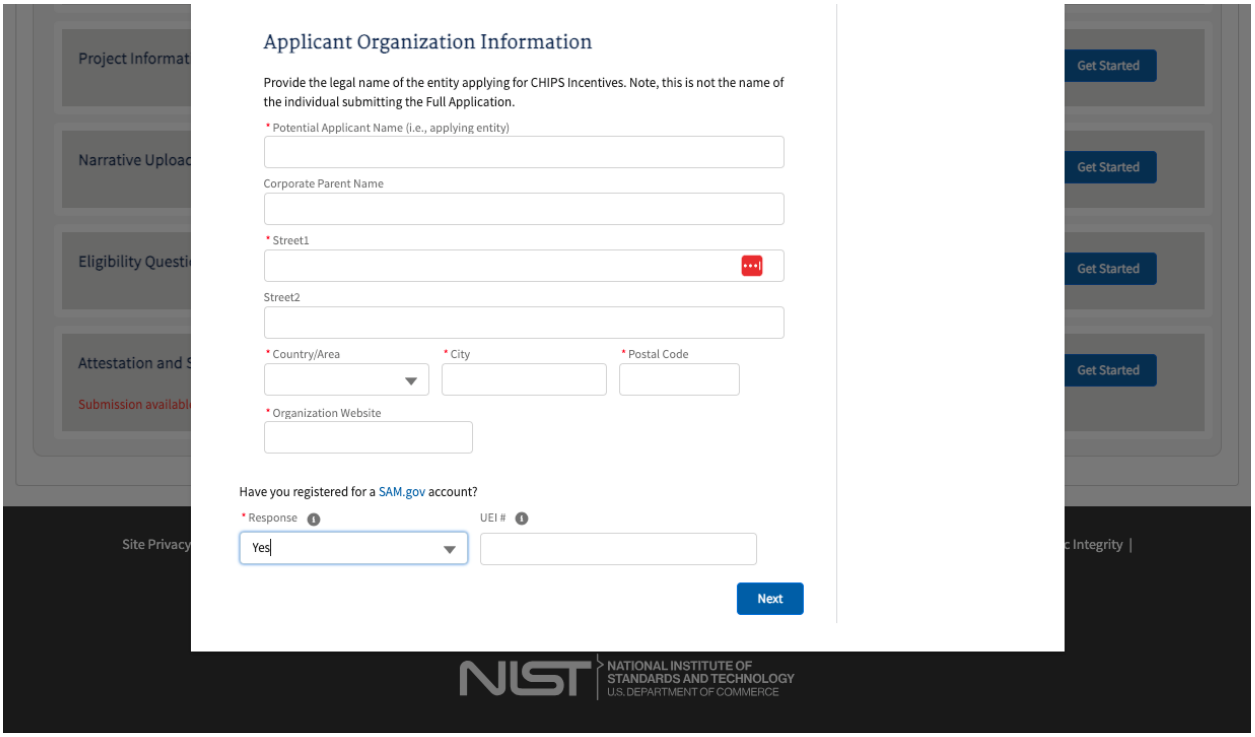
* Response

Picklist: Have you registered for a SAM.gov account?

Picklist Values:

- Yes
- No

Applicant Organization Information - *Have you registered for a Sam.gov account?* response is *Yes* shows *UEI#* field



Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Full Application.

* Potential Applicant Name (i.e., applying entity)

Corporate Parent Name

* Street1

Street2

* Country/Area

* City

* Postal Code

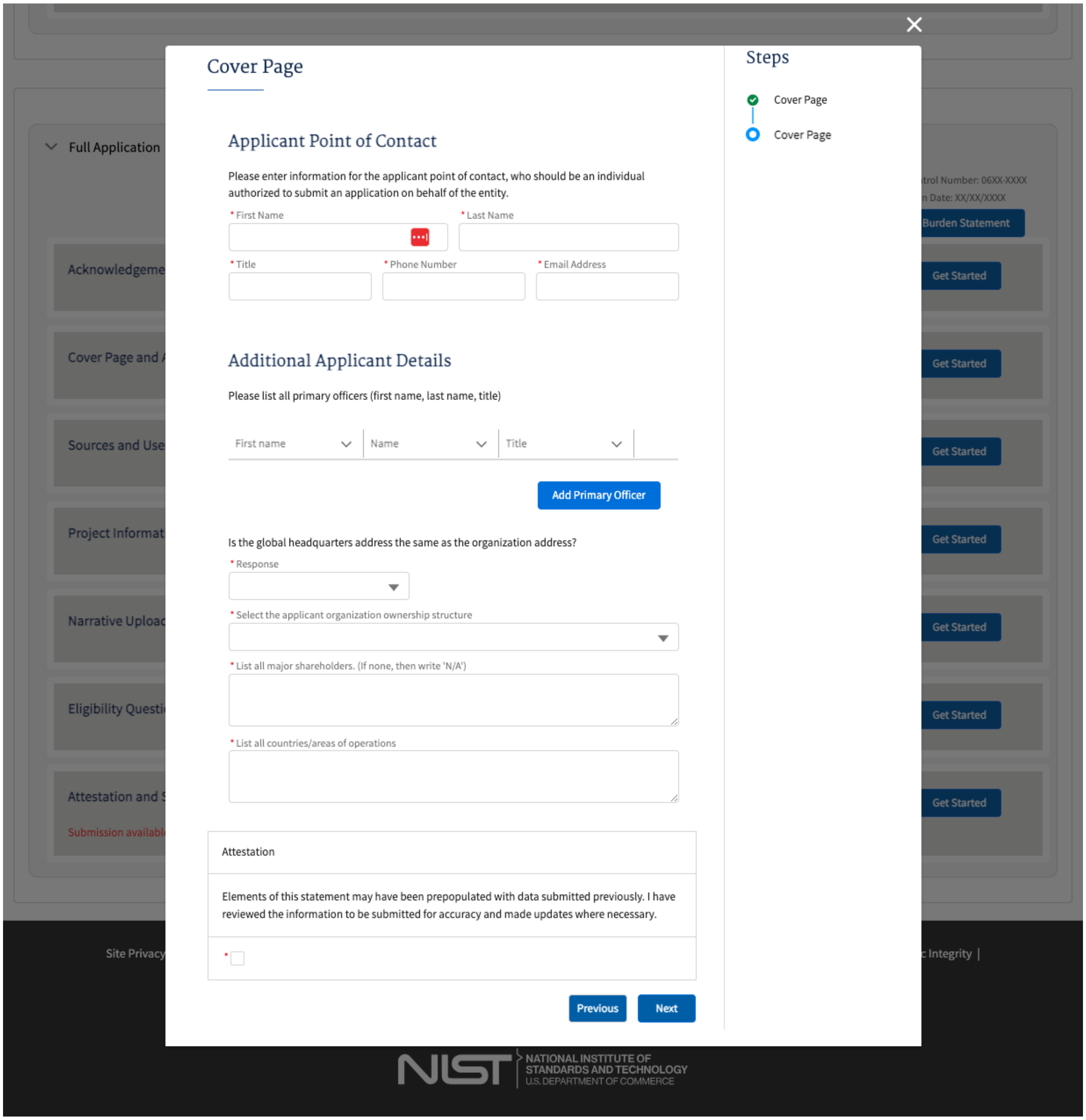
* Organization Website

Have you registered for a SAM.gov account?

* Response: Yes

UEI #

Applicant Point of Contact



Cover Page

Applicant Point of Contact

Please enter information for the applicant point of contact, who should be an individual authorized to submit an application on behalf of the entity.

* First Name ☐ * Last Name ☐

* Title ☐ * Phone Number ☐ * Email Address ☐

Additional Applicant Details

Please list all primary officers (first name, last name, title)

First name	Name	Title

Is the global headquarters address the same as the organization address?

* Response ☐

* Select the applicant organization ownership structure ☐

* List all major shareholders. (If none, then write 'N/A') ☐

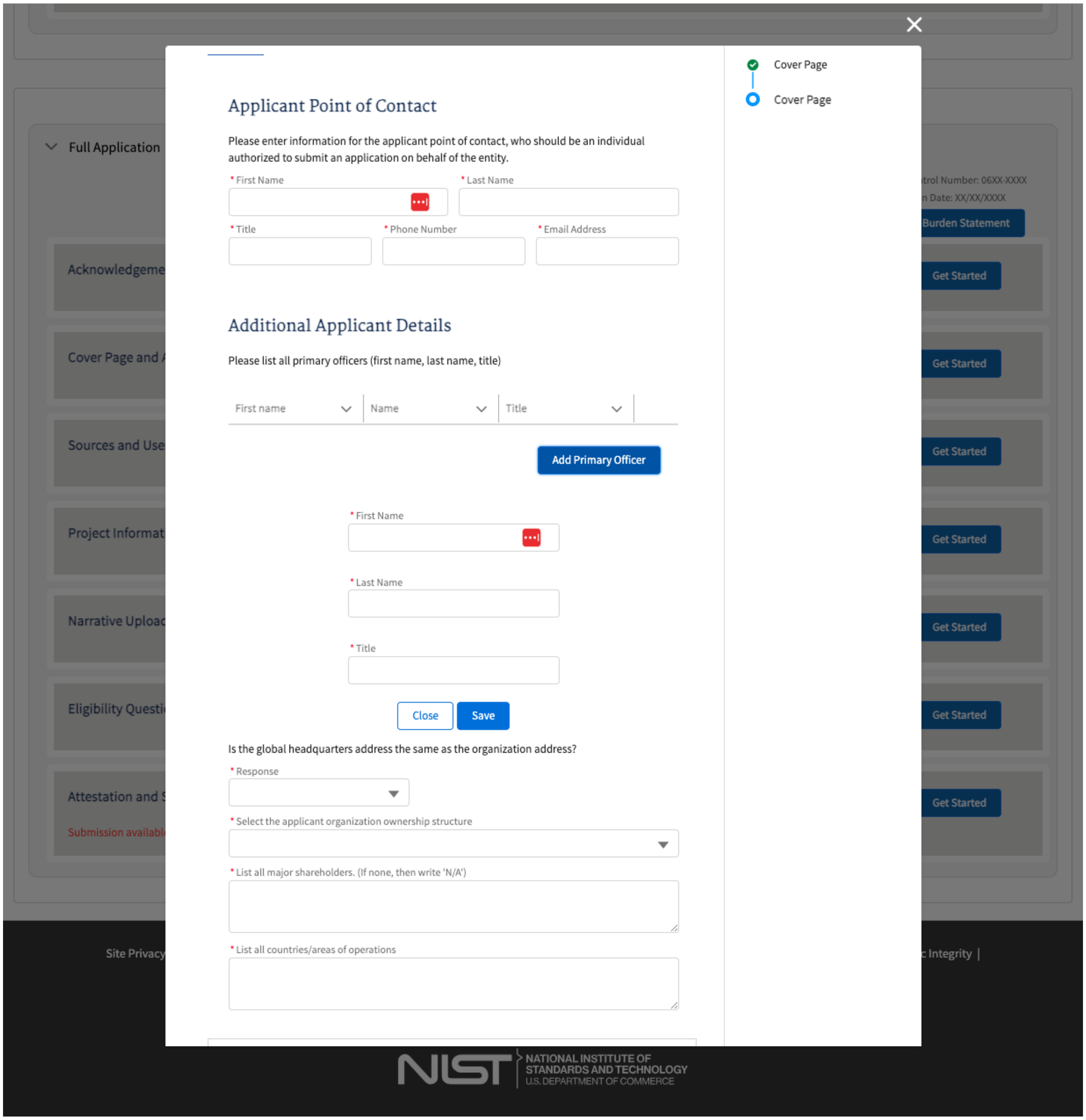
* List all countries/areas of operations ☐

Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

* ☐

Add Primary Officer



Applicant Point of Contact

Please enter information for the applicant point of contact, who should be an individual authorized to submit an application on behalf of the entity.

* First Name
* Last Name
* Title
* Phone Number
* Email Address

Additional Applicant Details

Please list all primary officers (first name, last name, title)

First name	Name	Title

* First Name
* Last Name
* Title

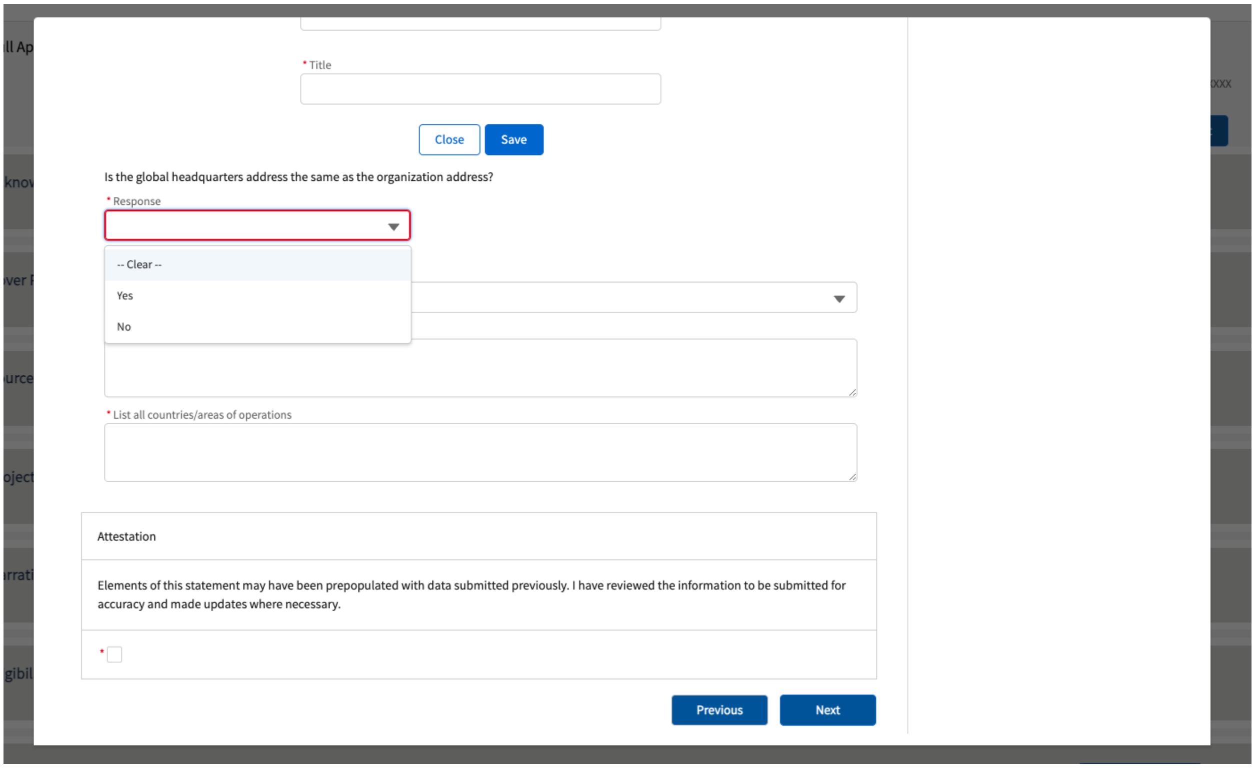
Is the global headquarters address the same as the organization address?

* Response

* Select the applicant organization ownership structure

* List all major shareholders. (If none, then write 'N/A')

* List all countries/areas of operations



Is the global headquarters address the same as the organization address?

Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

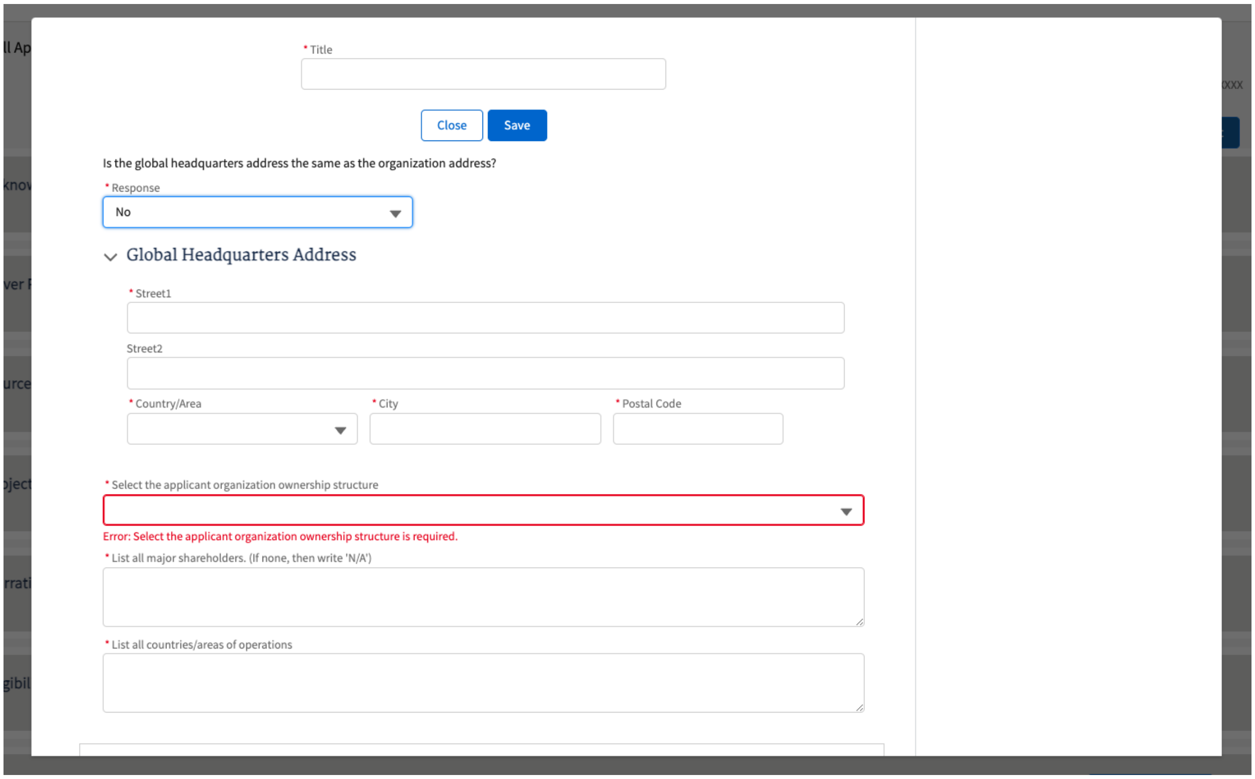
* ☐

Picklist: *Is Global Headquarters the same as the organization address?*

Picklist Values:

- Yes
- No

Is Global Headquarters the same as the organization address? Response is *No,* showing Global Address Headquarters input fields



* Title

Is the global headquarters address the same as the organization address?

* Response: No

Global Headquarters Address

* Street1

Street2

* Country/Area

* City

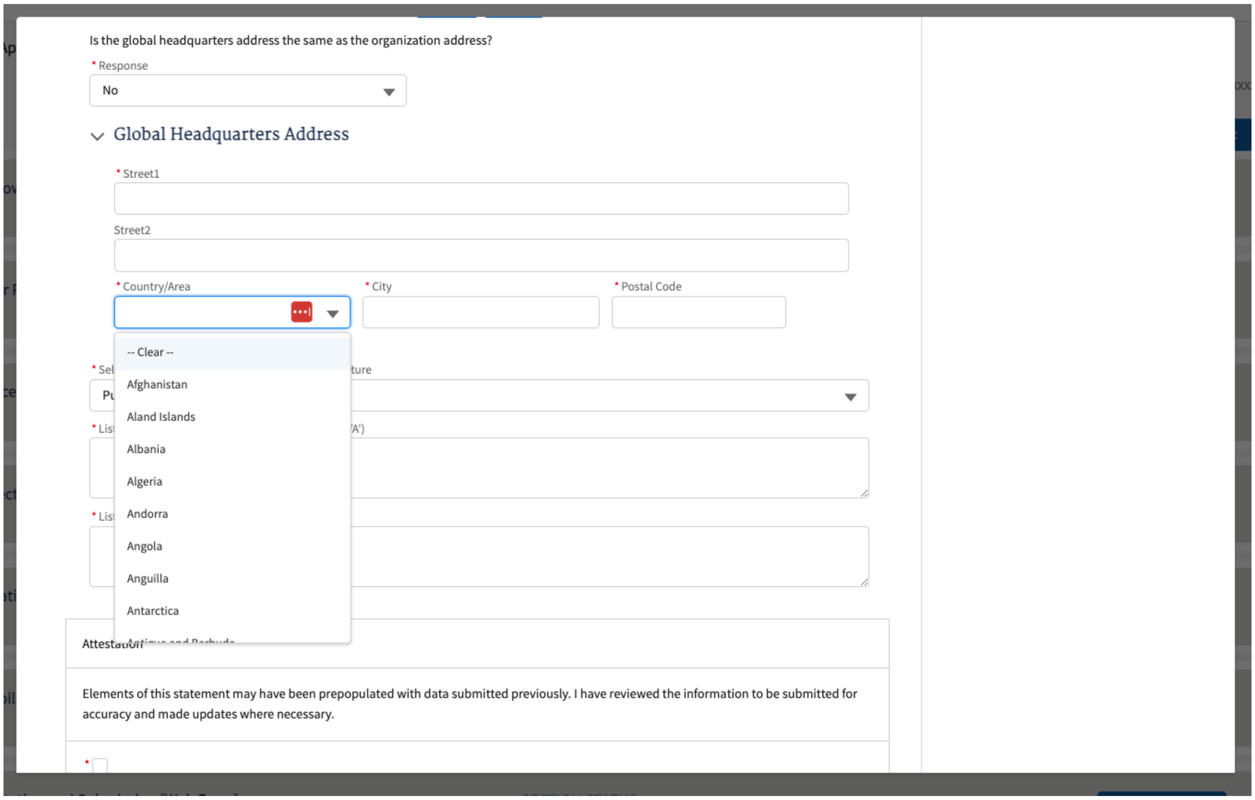
* Postal Code

* Select the applicant organization ownership structure

Error: Select the applicant organization ownership structure is required.

* List all major shareholders. (If none, then write 'N/A')

* List all countries/areas of operations



Is the global headquarters address the same as the organization address?

* Response: No

Global Headquarters Address

* Street1

Street2

* Country/Area

* City

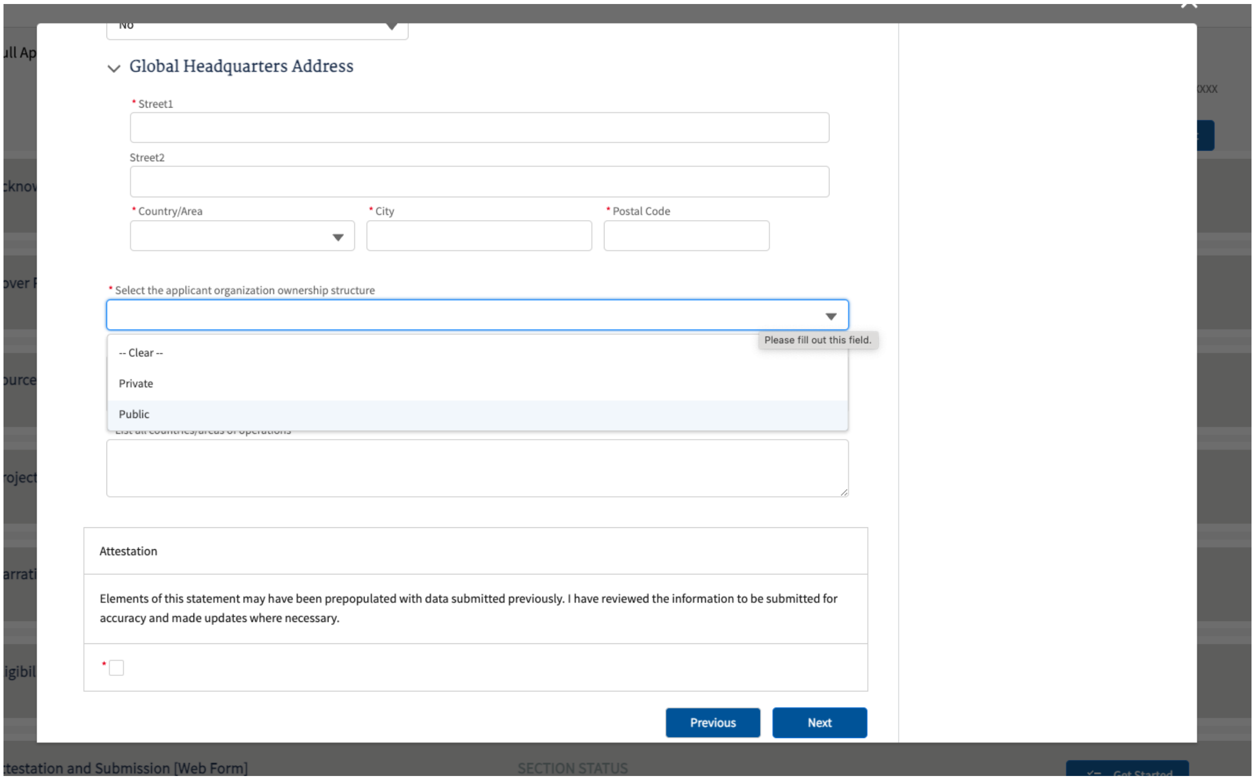
* Postal Code

Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

* ☐

Picklist: Country/Area
Picklist Values: Standard list of Countries



Global Headquarters Address

* Street1

Street2

* Country/Area

* City

* Postal Code

* Select the applicant organization ownership structure

List all countries/areas of operations

Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

* ☐

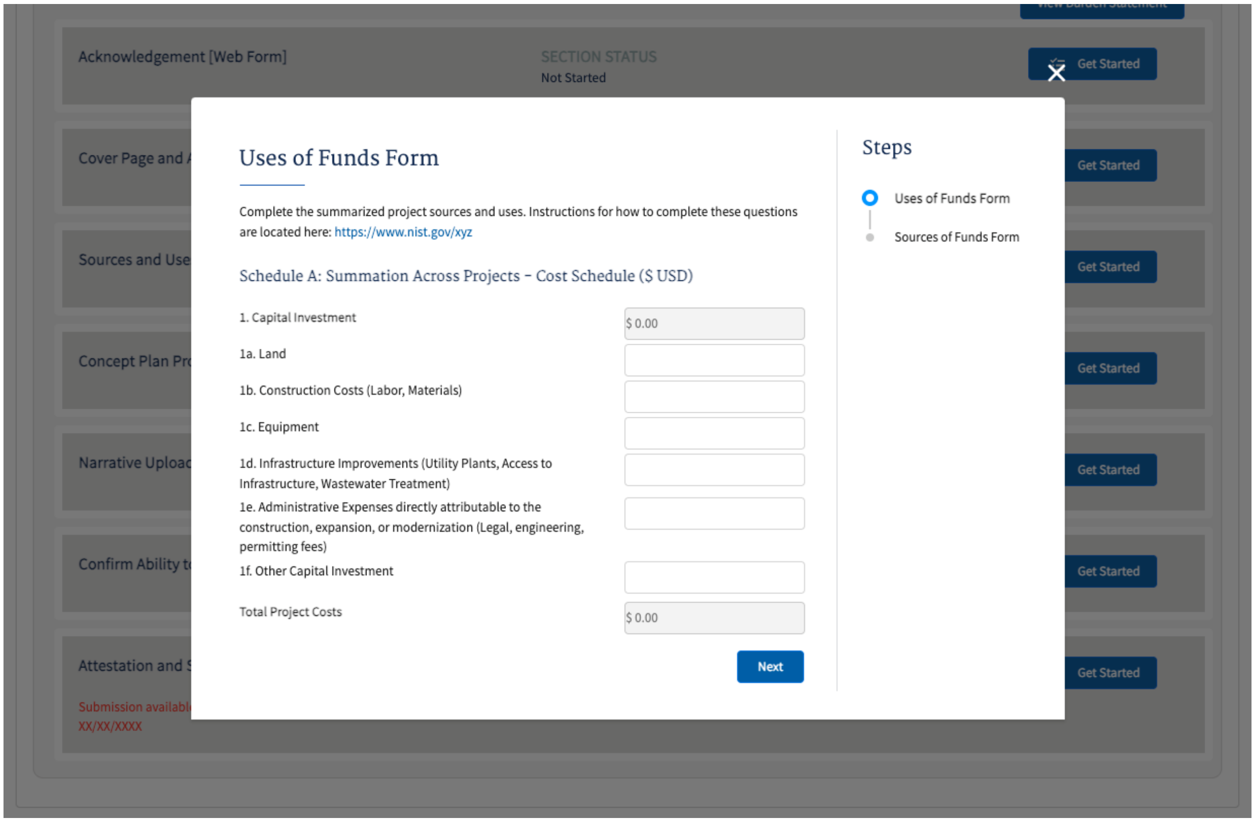
Picklist: Select the applicant organization ownership structure

Picklist Values:

- Private
- Public

Sources and Uses of Funds [Web Form]

Uses of Funds Form



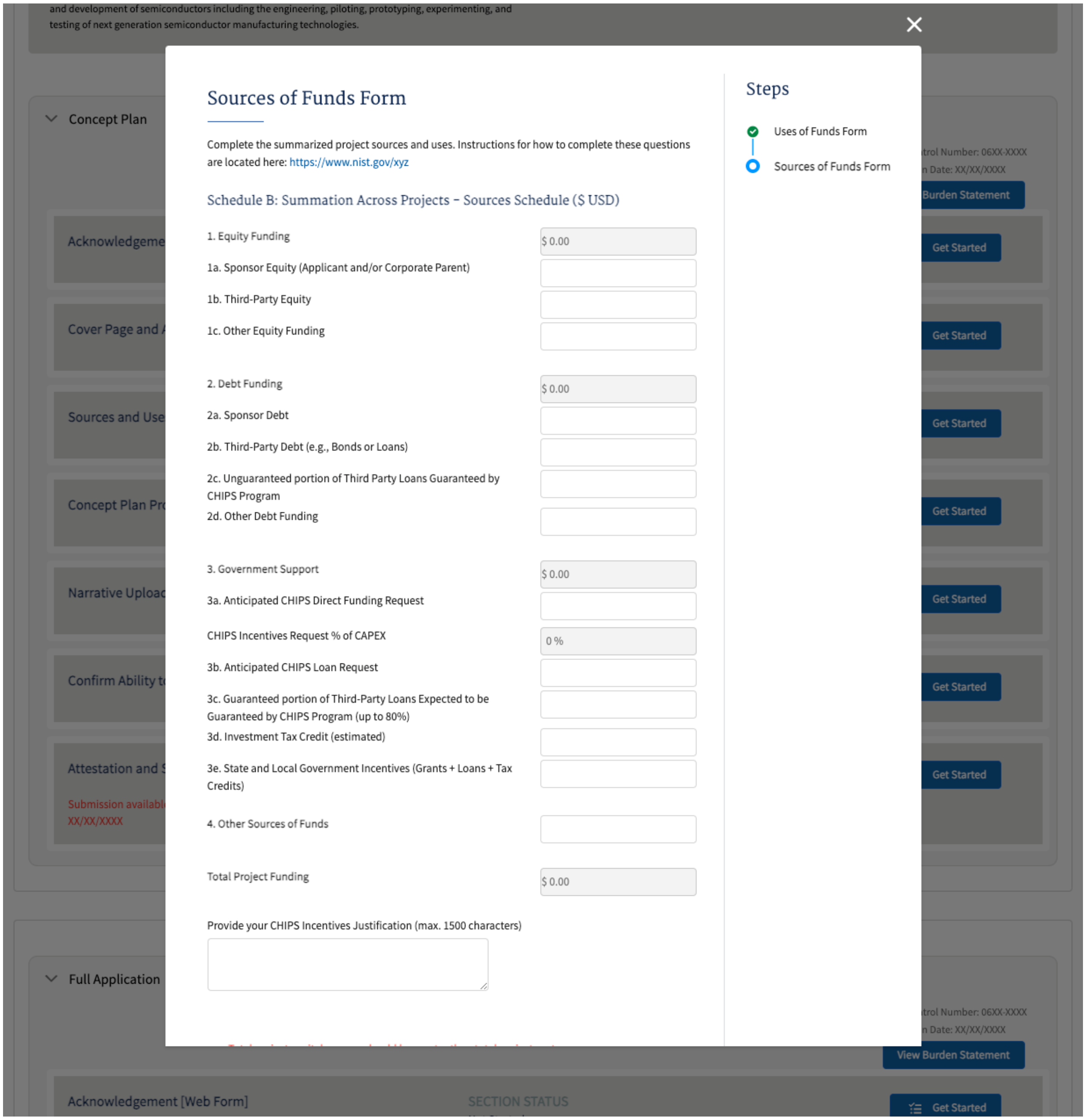
Uses of Funds Form

Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

Schedule A: Summation Across Projects – Cost Schedule ($ USD)

1. Capital Investment	$ 0.00
1a. Land	
1b. Construction Costs (Labor, Materials)	
1c. Equipment	
1d. Infrastructure Improvements (Utility Plants, Access to Infrastructure, Wastewater Treatment)	
1e. Administrative Expenses directly attributable to the construction, expansion, or modernization (Legal, engineering, permitting fees)	
1f. Other Capital Investment	
Total Project Costs	$ 0.00

Sources of Funds Form



Sources of Funds Form

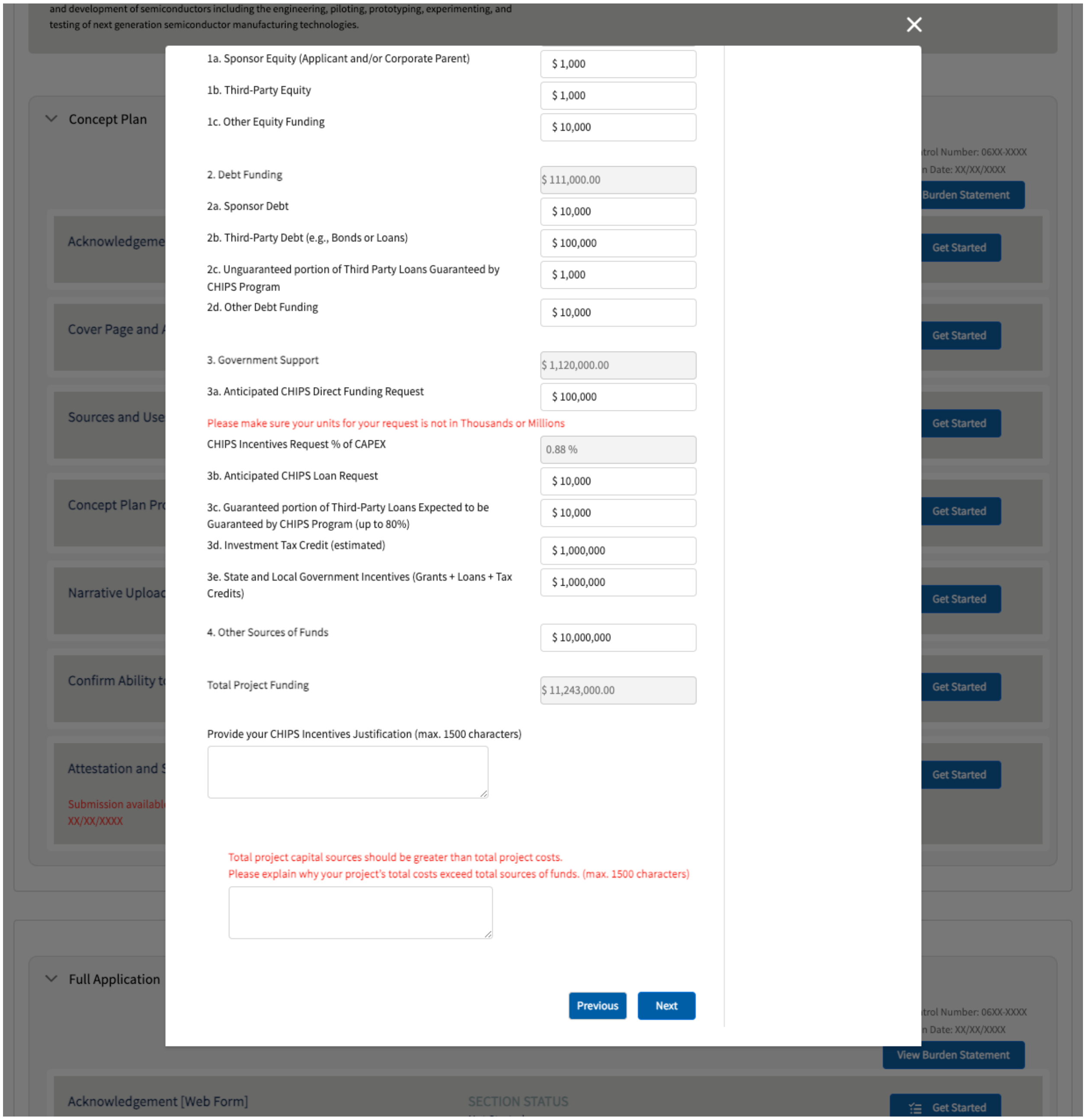
Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

Schedule B: Summation Across Projects – Sources Schedule ($ USD)

1. Equity Funding	$ 0.00
1a. Sponsor Equity (Applicant and/or Corporate Parent)	
1b. Third-Party Equity	
1c. Other Equity Funding	
2. Debt Funding	$ 0.00
2a. Sponsor Debt	
2b. Third-Party Debt (e.g., Bonds or Loans)	
2c. Unguaranteed portion of Third Party Loans Guaranteed by CHIPS Program	
2d. Other Debt Funding	
3. Government Support	$ 0.00
3a. Anticipated CHIPS Direct Funding Request	
CHIPS Incentives Request % of CAPEX	0 %
3b. Anticipated CHIPS Loan Request	
3c. Guaranteed portion of Third-Party Loans Expected to be Guaranteed by CHIPS Program (up to 80%)	
3d. Investment Tax Credit (estimated)	
3e. State and Local Government Incentives (Grants + Loans + Tax Credits)	
4. Other Sources of Funds	
Total Project Funding	$ 0.00

Provide your CHIPS Incentives Justification (max. 1500 characters)

Sources of Funds disclaimer regarding project capital expenditures: *If Total Project Funding is less than Total Project Costs*


and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.

1a. Sponsor Equity (Applicant and/or Corporate Parent)	$ 1,000
1b. Third-Party Equity	$ 1,000
1c. Other Equity Funding	$ 10,000
2. Debt Funding	$ 111,000.00
2a. Sponsor Debt	$ 10,000
2b. Third-Party Debt (e.g., Bonds or Loans)	$ 100,000
2c. Unguaranteed portion of Third Party Loans Guaranteed by CHIPS Program	$ 1,000
2d. Other Debt Funding	$ 10,000
3. Government Support	$ 1,120,000.00
3a. Anticipated CHIPS Direct Funding Request	$ 100,000

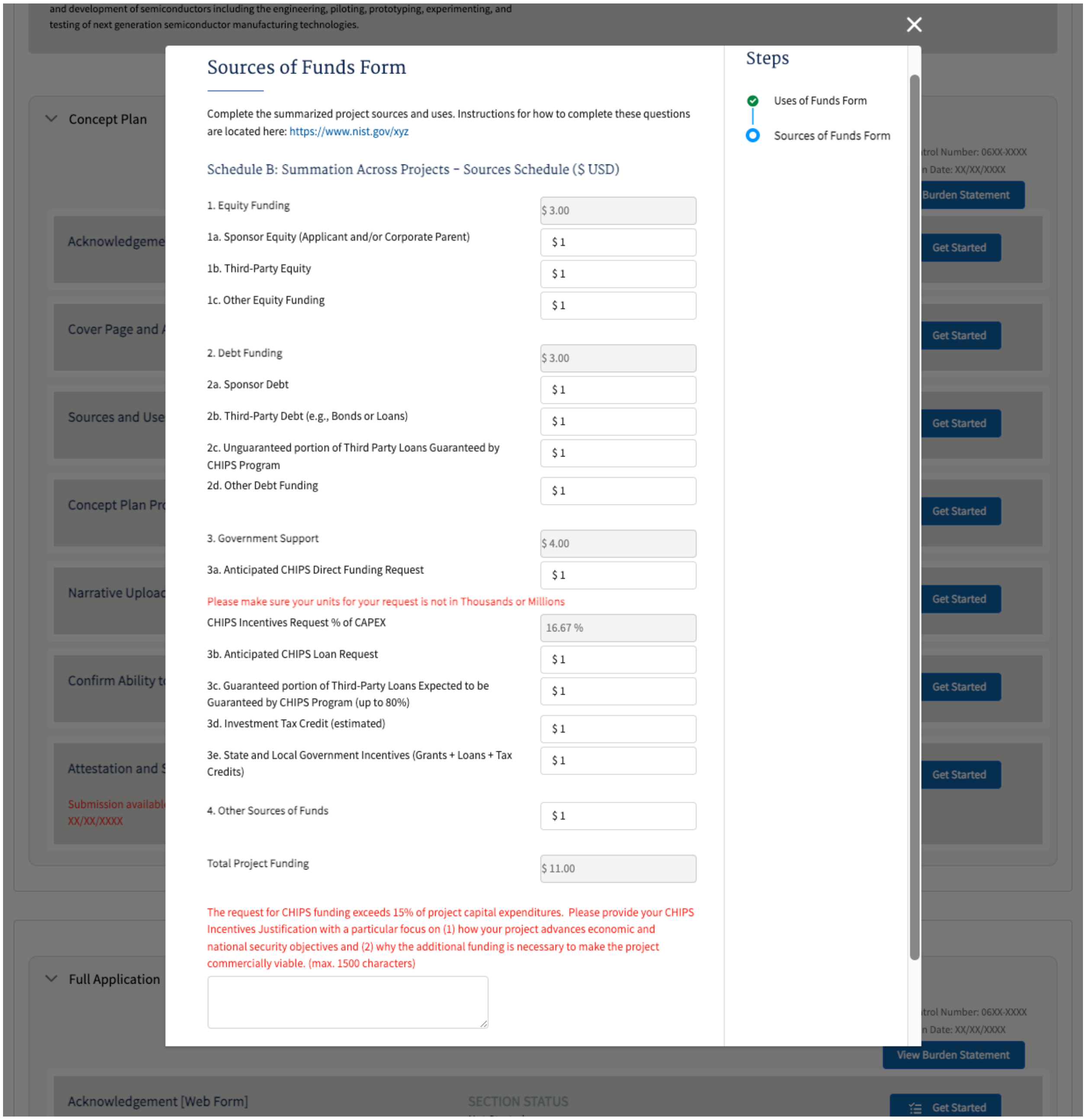
Please make sure your units for your request is not in Thousands or Millions

CHIPS Incentives Request % of CAPEX	0.88 %
3b. Anticipated CHIPS Loan Request	$ 10,000
3c. Guaranteed portion of Third-Party Loans Expected to be Guaranteed by CHIPS Program (up to 80%)	$ 10,000
3d. Investment Tax Credit (estimated)	$ 1,000,000
3e. State and Local Government Incentives (Grants + Loans + Tax Credits)	$ 1,000,000
4. Other Sources of Funds	$ 10,000,000
Total Project Funding	$ 11,243,000.00

Provide your CHIPS Incentives Justification (max. 1500 characters)

Total project capital sources should be greater than total project costs.
Please explain why your project's total costs exceed total sources of funds. (max. 1500 characters)

Sources of Funds disclaimer regarding project capital expenditures: *If Anticipated CHIPS Direct Funding Request/Total Capital Investments exceeds 15%*



and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.

Sources of Funds Form

Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

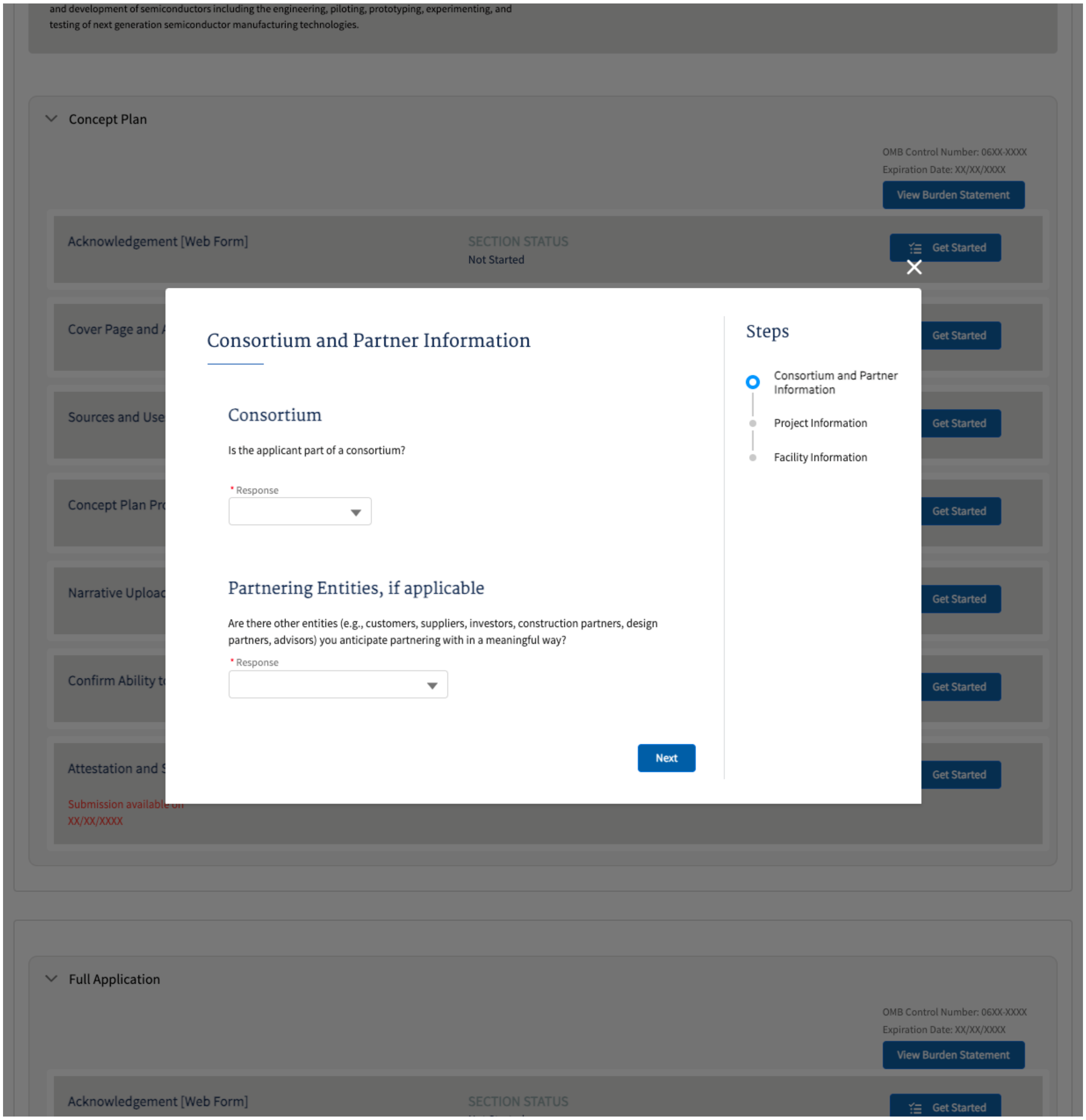
Schedule B: Summation Across Projects – Sources Schedule ($ USD)

1. Equity Funding	$ 3.00
1a. Sponsor Equity (Applicant and/or Corporate Parent)	$ 1
1b. Third-Party Equity	$ 1
1c. Other Equity Funding	$ 1
2. Debt Funding	$ 3.00
2a. Sponsor Debt	$ 1
2b. Third-Party Debt (e.g., Bonds or Loans)	$ 1
2c. Unguaranteed portion of Third Party Loans Guaranteed by CHIPS Program	$ 1
2d. Other Debt Funding	$ 1
3. Government Support	$ 4.00
3a. Anticipated CHIPS Direct Funding Request	$ 1
Please make sure your units for your request is not in Thousands or Millions	
CHIPS Incentives Request % of CAPEX	16.67 %
3b. Anticipated CHIPS Loan Request	$ 1
3c. Guaranteed portion of Third-Party Loans Expected to be Guaranteed by CHIPS Program (up to 80%)	$ 1
3d. Investment Tax Credit (estimated)	$ 1
3e. State and Local Government Incentives (Grants + Loans + Tax Credits)	$ 1
4. Other Sources of Funds	$ 1
Total Project Funding	$ 11.00

The request for CHIPS funding exceeds 15% of project capital expenditures. Please provide your CHIPS Incentives Justification with a particular focus on (1) how your project advances economic and national security objectives and (2) why the additional funding is necessary to make the project commercially viable. (max. 1500 characters)

Concept Plan Project Information [Web Form]

Consortium and Partner Information



and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.

Concept Plan

OMB Control Number: 06XX-XXXX
Expiration Date: XX/XX/XXXX

Acknowledgement [Web Form] — SECTION STATUS: Not Started

Cover Page and

Sources and Use

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Attestation and

Submission available on XX/XX/XXXX

Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

Partnering Entities, if applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response

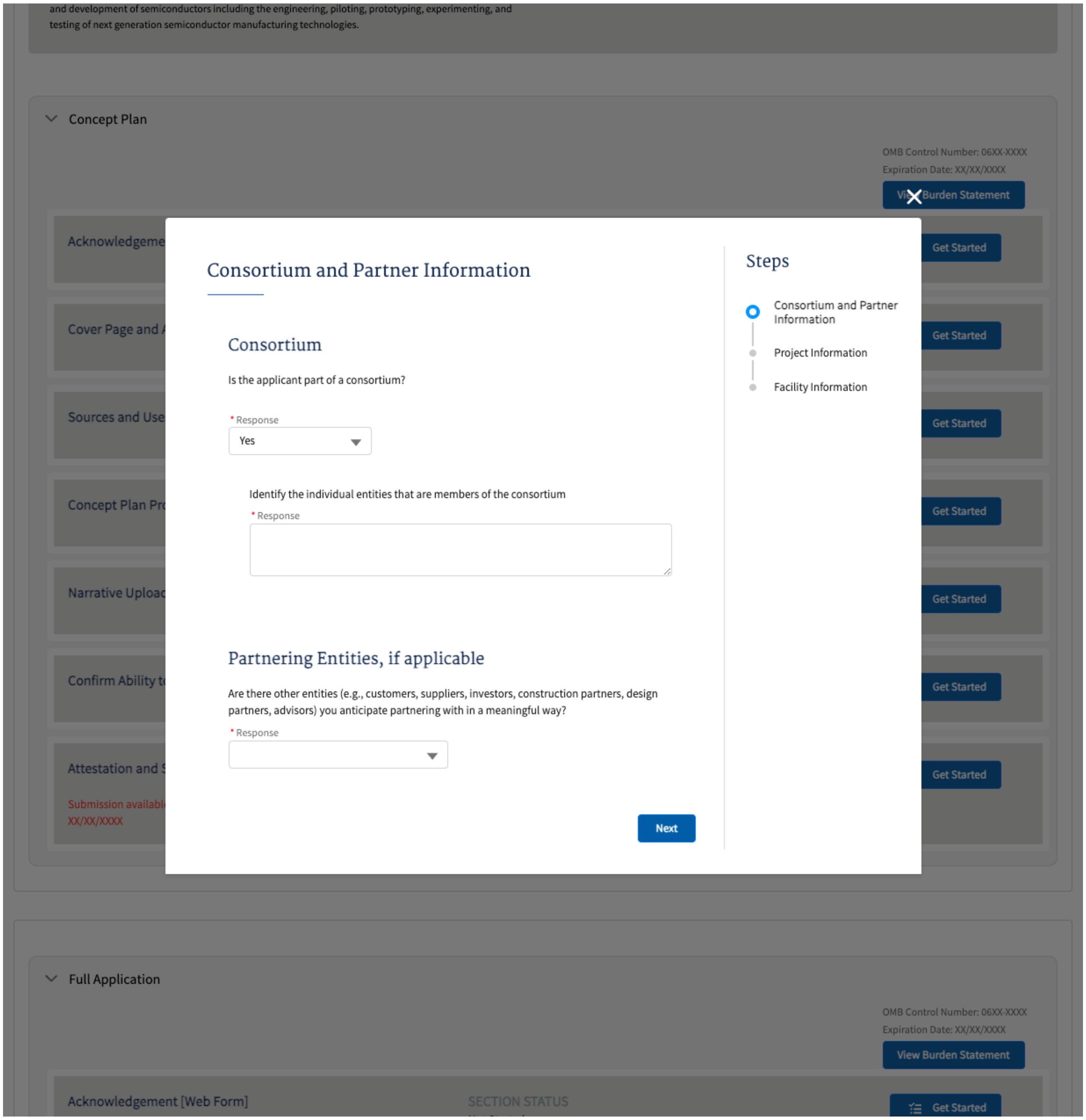
Steps

- Consortium and Partner Information
- Project Information
- Facility Information

Full Application

OMB Control Number: 06XX-XXXX
Expiration Date: XX/XX/XXXX

Acknowledgement [Web Form] — SECTION STATUS



and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.

Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response: Yes

Identify the individual entities that are members of the consortium

* Response:

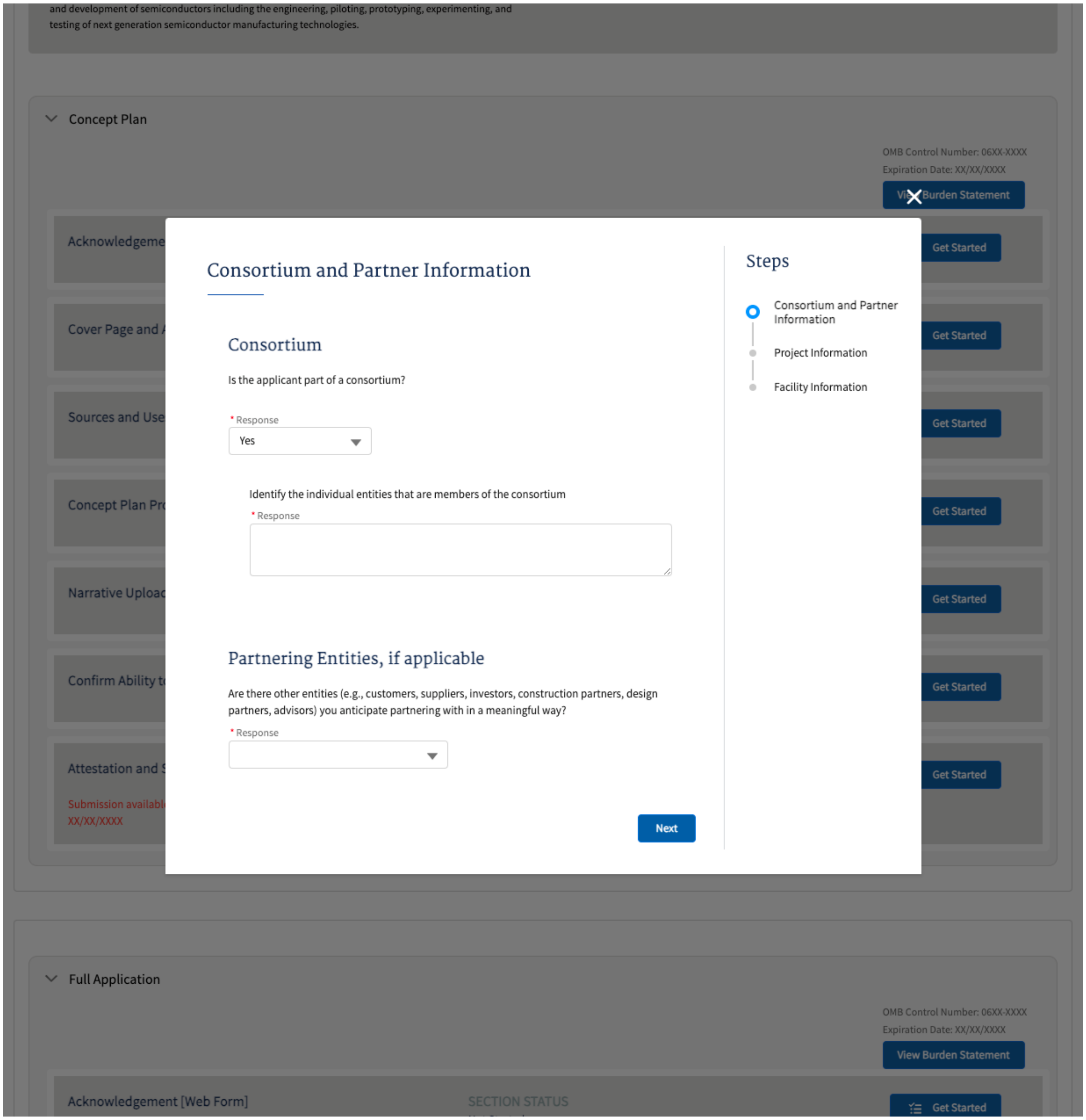
Partnering Entities, if applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response:

Picklist: Is the applicant part of a consortium?
Picklist Values:
- Yes
- No

Is the applicant part of a consortium? Response is *Yes* prompts *Identify the individual entities that are members of the consortium*



and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.

Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

Yes

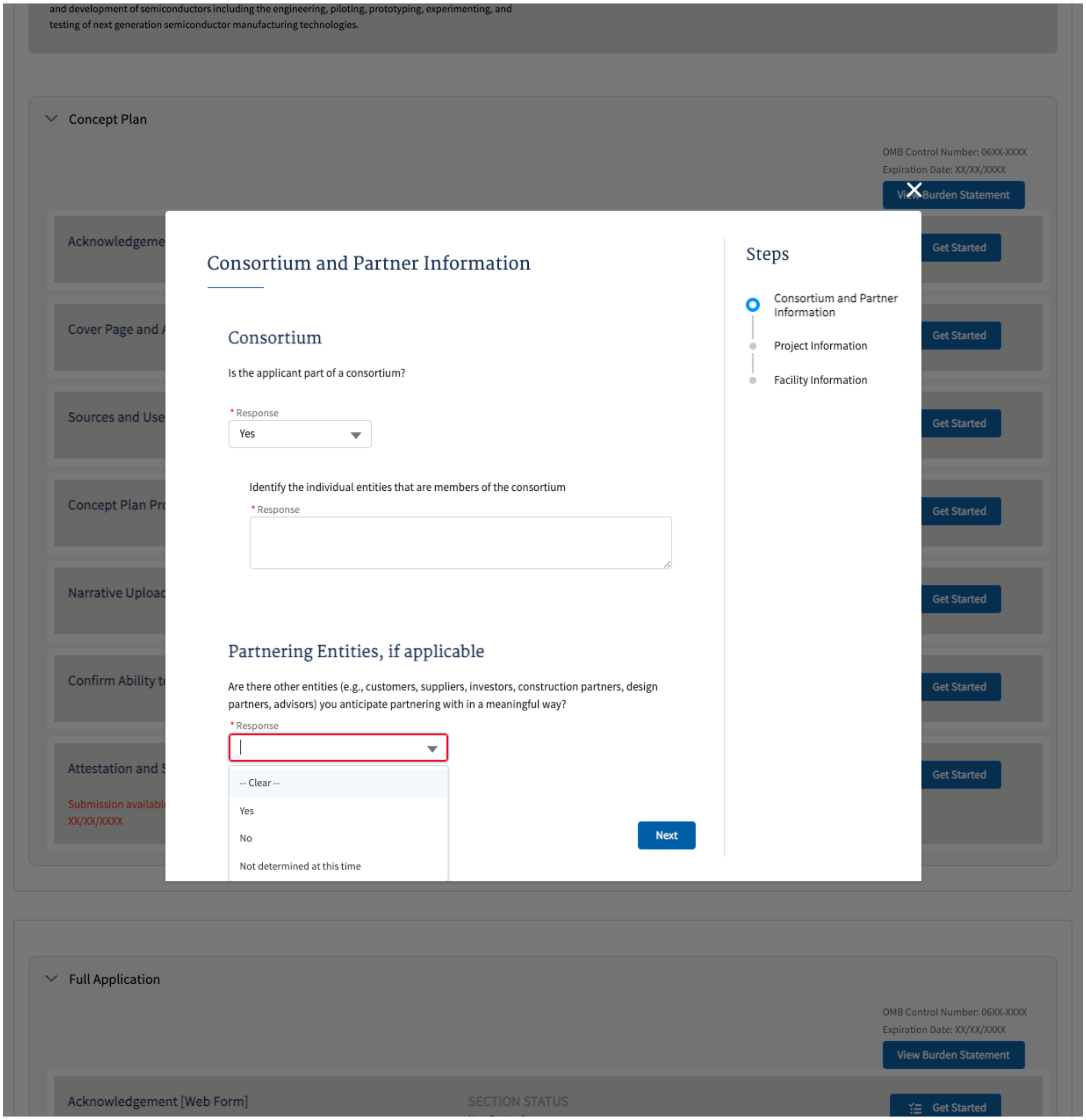
Identify the individual entities that are members of the consortium

* Response

Partnering Entities, if applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response



Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response: Yes

Identify the individual entities that are members of the consortium

* Response

Partnering Entities, if applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response

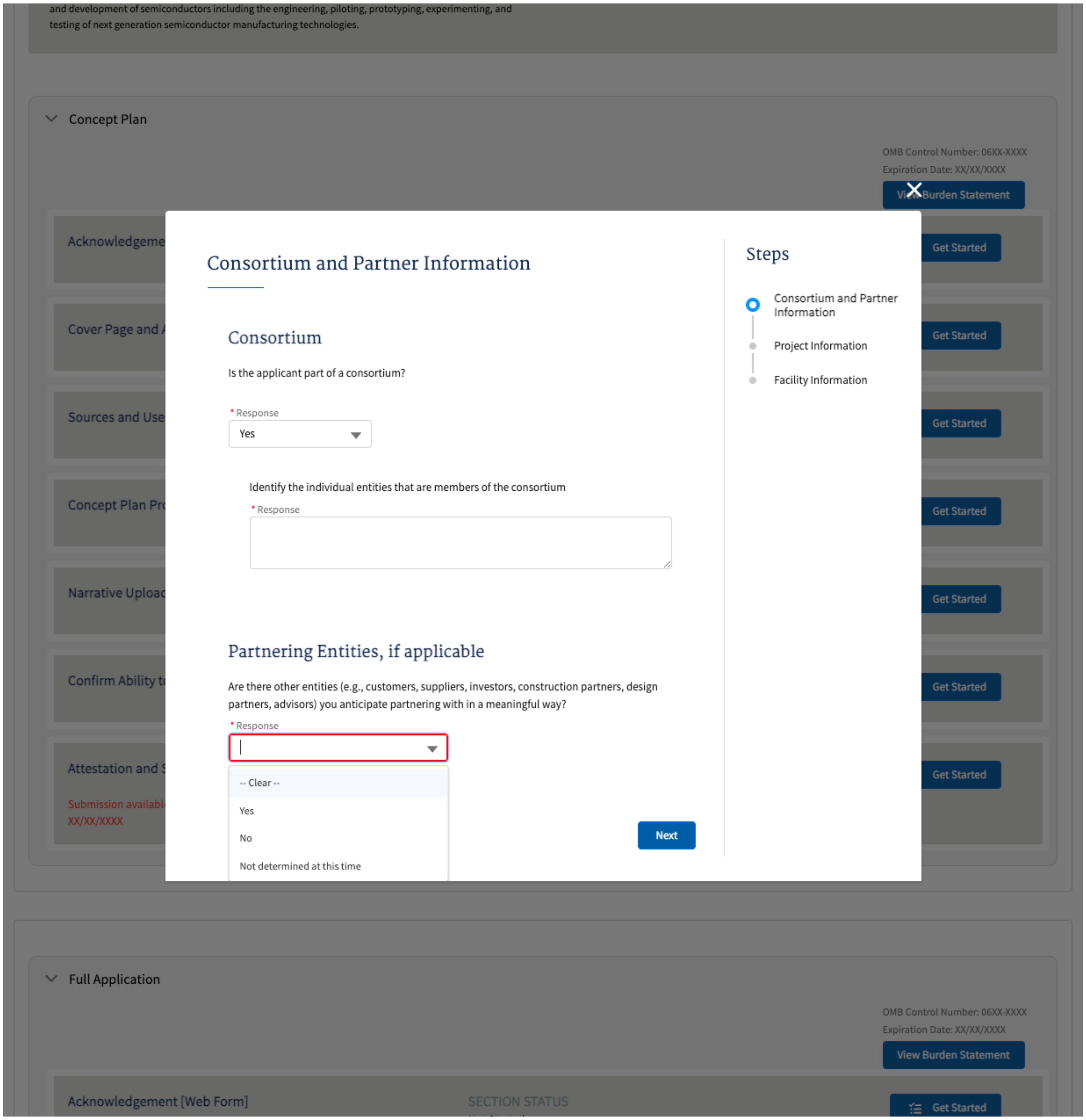
-- Clear --
Yes
No
Not determined at this time

Picklist: Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

Picklist Values:

- Yes
- No
- Not determined at this time

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way? Response of *Yes* prompts *Please list each partner and describe their role in the project*



Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response: Yes

Identify the individual entities that are members of the consortium

* Response

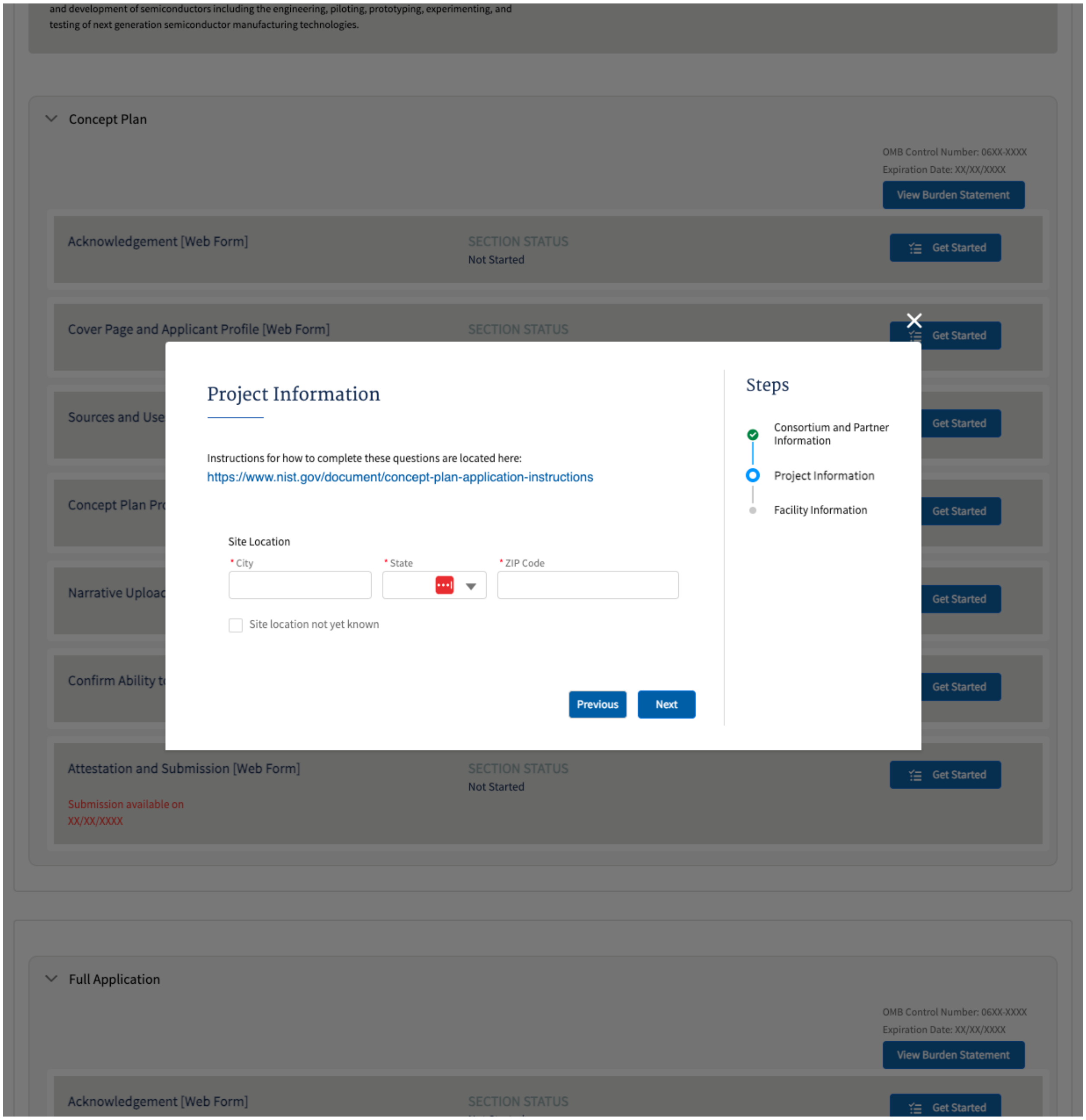
Partnering Entities, if applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response

-- Clear --
Yes
No
Not determined at this time

Project Information



and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.

Concept Plan

OMB Control Number: 06XX-XXXX
Expiration Date: XX/XX/XXXX

View Burden Statement

Acknowledgement [Web Form]	SECTION STATUS Not Started	Get Started
Cover Page and Applicant Profile [Web Form]	SECTION STATUS	Get Started
Sources and Use		Get Started
Concept Plan Pr		Get Started
Narrative Uploa		Get Started
Confirm Ability t		Get Started
Attestation and Submission [Web Form] Submission available on XX/XX/XXXX	SECTION STATUS Not Started	Get Started

Project Information

Instructions for how to complete these questions are located here:
https://www.nist.gov/document/concept-plan-application-instructions

Site Location

* City	* State	* ZIP Code

☐ Site location not yet known

Previous Next

Steps

- ✓ Consortium and Partner Information
- ○ Project Information
- ● Facility Information

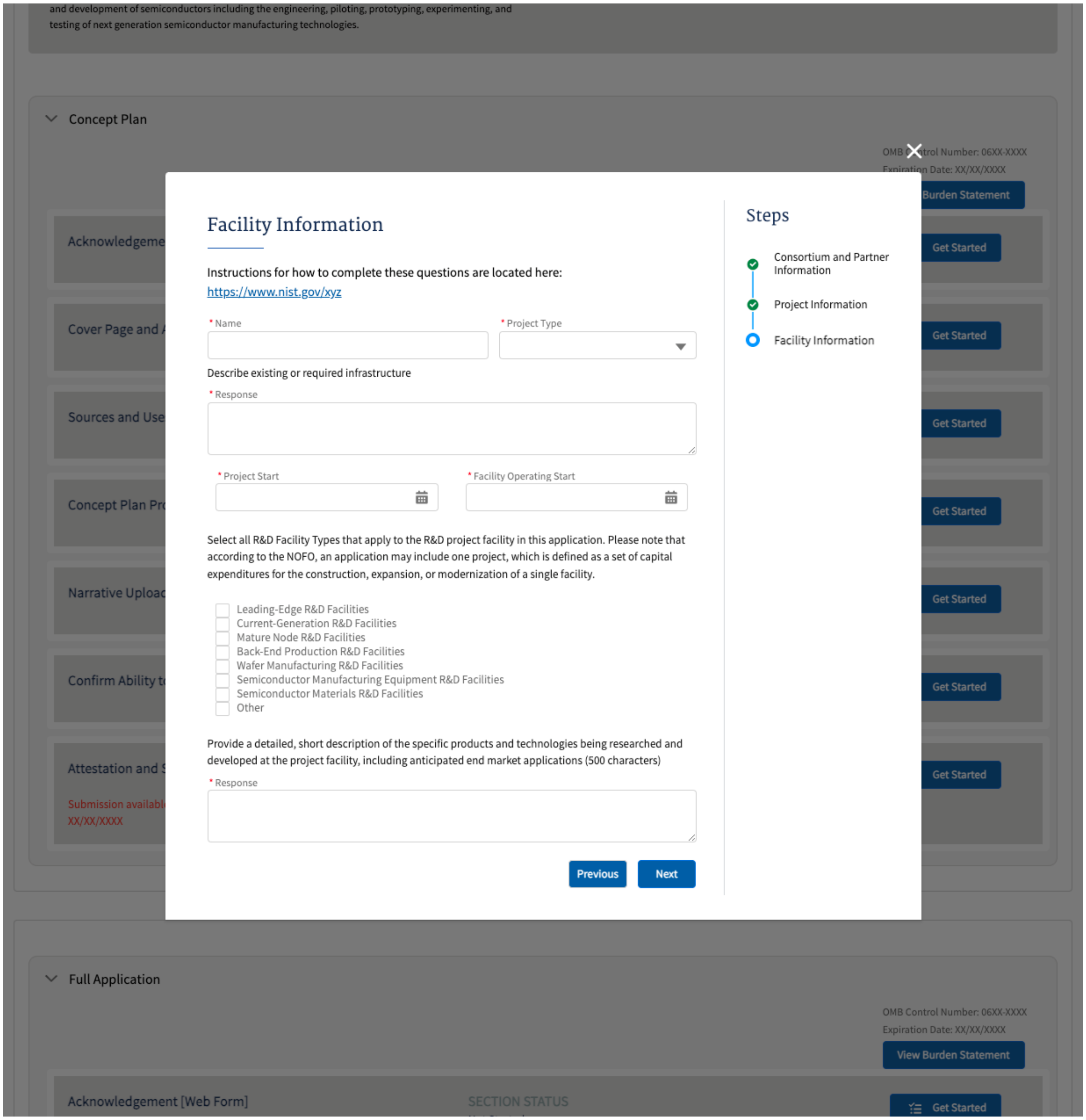
Full Application

OMB Control Number: 06XX-XXXX
Expiration Date: XX/XX/XXXX

View Burden Statement

Acknowledgement [Web Form]	SECTION STATUS	Get Started

Facility Information



and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.

Concept Plan

OMB Control Number: 06XX-XXXX
Expiration Date: XX/XX/XXXX

Facility Information

Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

* Name

* Project Type

Describe existing or required infrastructure

* Response

* Project Start

* Facility Operating Start

Select all R&D Facility Types that apply to the R&D project facility in this application. Please note that according to the NOFO, an application may include one project, which is defined as a set of capital expenditures for the construction, expansion, or modernization of a single facility.

- ☐ Leading-Edge R&D Facilities
- ☐ Current-Generation R&D Facilities
- ☐ Mature Node R&D Facilities
- ☐ Back-End Production R&D Facilities
- ☐ Wafer Manufacturing R&D Facilities
- ☐ Semiconductor Manufacturing Equipment R&D Facilities
- ☐ Semiconductor Materials R&D Facilities
- ☐ Other

Provide a detailed, short description of the specific products and technologies being researched and developed at the project facility, including anticipated end market applications (500 characters)

* Response

Steps

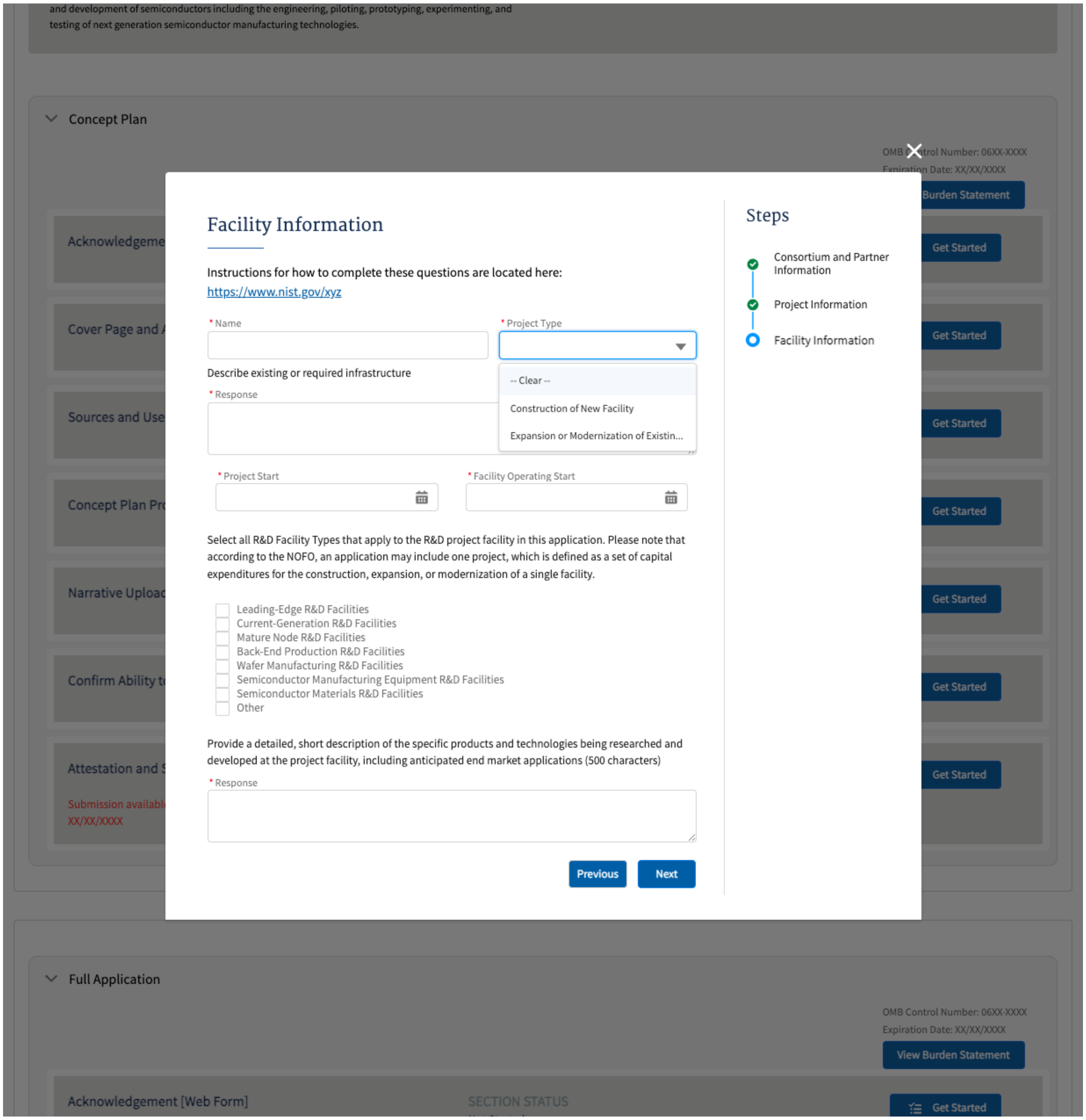
- Consortium and Partner Information
- Project Information
- Facility Information

Submission available XX/XX/XXXX

Full Application

OMB Control Number: 06XX-XXXX
Expiration Date: XX/XX/XXXX

Acknowledgement [Web Form] SECTION STATUS



Facility Information

Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

* Name

* Project Type

Describe existing or required infrastructure

* Response

-- Clear --
Construction of New Facility
Expansion or Modernization of Existin...

* Project Start

* Facility Operating Start

Select all R&D Facility Types that apply to the R&D project facility in this application. Please note that according to the NOFO, an application may include one project, which is defined as a set of capital expenditures for the construction, expansion, or modernization of a single facility.

☐ Leading-Edge R&D Facilities
☐ Current-Generation R&D Facilities
☐ Mature Node R&D Facilities
☐ Back-End Production R&D Facilities
☐ Wafer Manufacturing R&D Facilities
☐ Semiconductor Manufacturing Equipment R&D Facilities
☐ Semiconductor Materials R&D Facilities
☐ Other

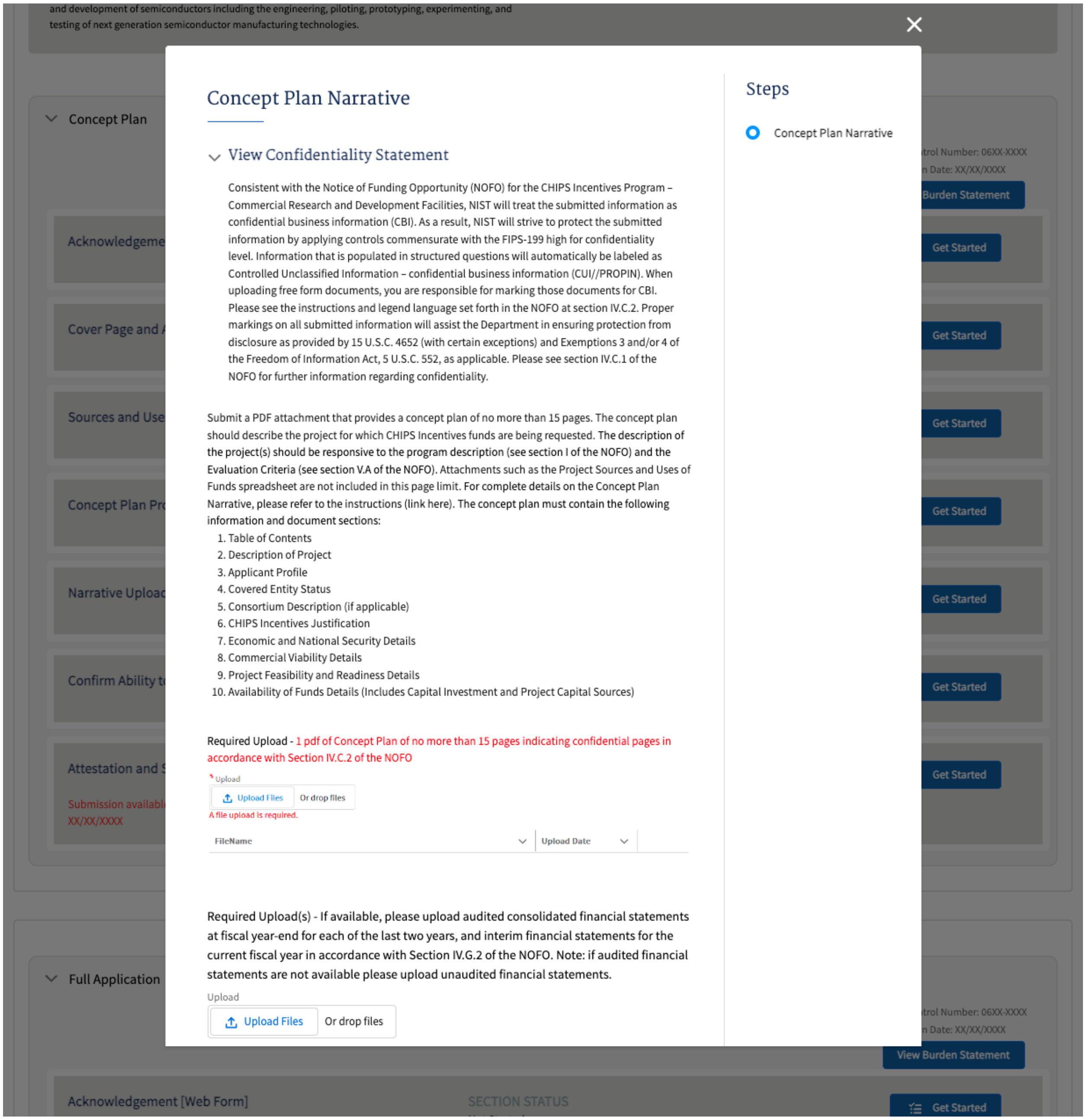
Provide a detailed, short description of the specific products and technologies being researched and developed at the project facility, including anticipated end market applications (500 characters)

* Response

Picklist: Project Type
Picklist Values:

- Construction of New Facility
- Expansion or Modernization of Existing Facility

Narrative Uploads



Concept Plan Narrative

View Confidentiality Statement

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Commercial Research and Development Facilities, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

Submit a PDF attachment that provides a concept plan of no more than 15 pages. The concept plan should describe the project for which CHIPS Incentives funds are being requested. The description of the project(s) should be responsive to the program description (see section I of the NOFO) and the Evaluation Criteria (see section V.A of the NOFO). Attachments such as the Project Sources and Uses of Funds spreadsheet are not included in this page limit. For complete details on the Concept Plan Narrative, please refer to the instructions (link here). The concept plan must contain the following information and document sections:

1. Table of Contents
2. Description of Project
3. Applicant Profile
4. Covered Entity Status
5. Consortium Description (if applicable)
6. CHIPS Incentives Justification
7. Economic and National Security Details
8. Commercial Viability Details
9. Project Feasibility and Readiness Details
10. Availability of Funds Details (Includes Capital Investment and Project Capital Sources)

Required Upload - 1 pdf of Concept Plan of no more than 15 pages indicating confidential pages in accordance with Section IV.C.2 of the NOFO

* Upload

Upload Files | Or drop files

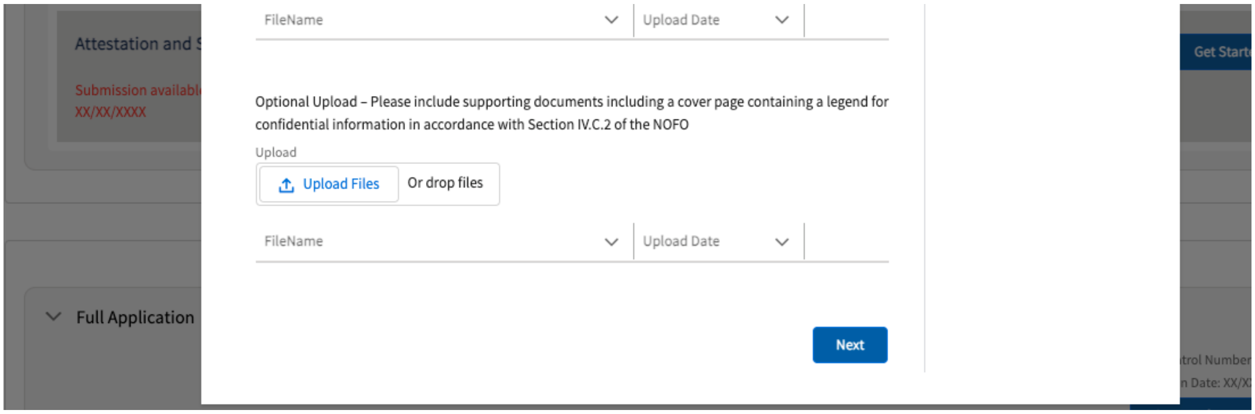
A file upload is required.

FileName	Upload Date

Required Upload(s) - If available, please upload audited consolidated financial statements at fiscal year-end for each of the last two years, and interim financial statements for the current fiscal year in accordance with Section IV.G.2 of the NOFO. Note: if audited financial statements are not available please upload unaudited financial statements.

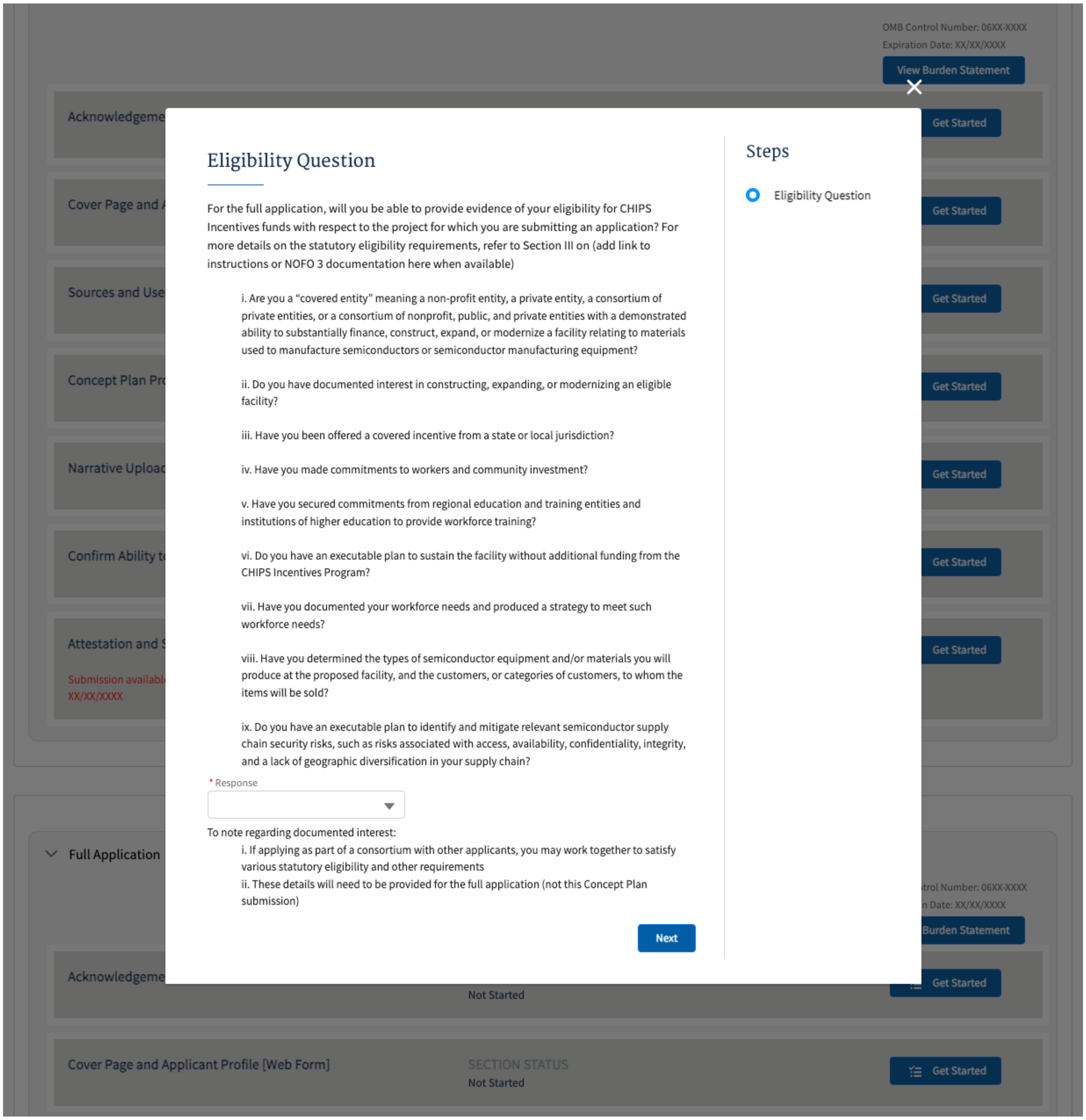
Upload

Upload Files | Or drop files



Optional Upload – Please include supporting documents including a cover page containing a legend for confidential information in accordance with Section IV.C.2 of the NOFO

Ability to Submit a Full Application [Web Form]



Eligibility Question

For the full application, will you be able to provide evidence of your eligibility for CHIPS Incentives funds with respect to the project for which you are submitting an application? For more details on the statutory eligibility requirements, refer to Section III on (add link to instructions or NOFO 3 documentation here when available)

i. Are you a "covered entity" meaning a non-profit entity, a private entity, a consortium of private entities, or a consortium of nonprofit, public, and private entities with a demonstrated ability to substantially finance, construct, expand, or modernize a facility relating to materials used to manufacture semiconductors or semiconductor manufacturing equipment?

ii. Do you have documented interest in constructing, expanding, or modernizing an eligible facility?

iii. Have you been offered a covered incentive from a state or local jurisdiction?

iv. Have you made commitments to workers and community investment?

v. Have you secured commitments from regional education and training entities and institutions of higher education to provide workforce training?

vi. Do you have an executable plan to sustain the facility without additional funding from the CHIPS Incentives Program?

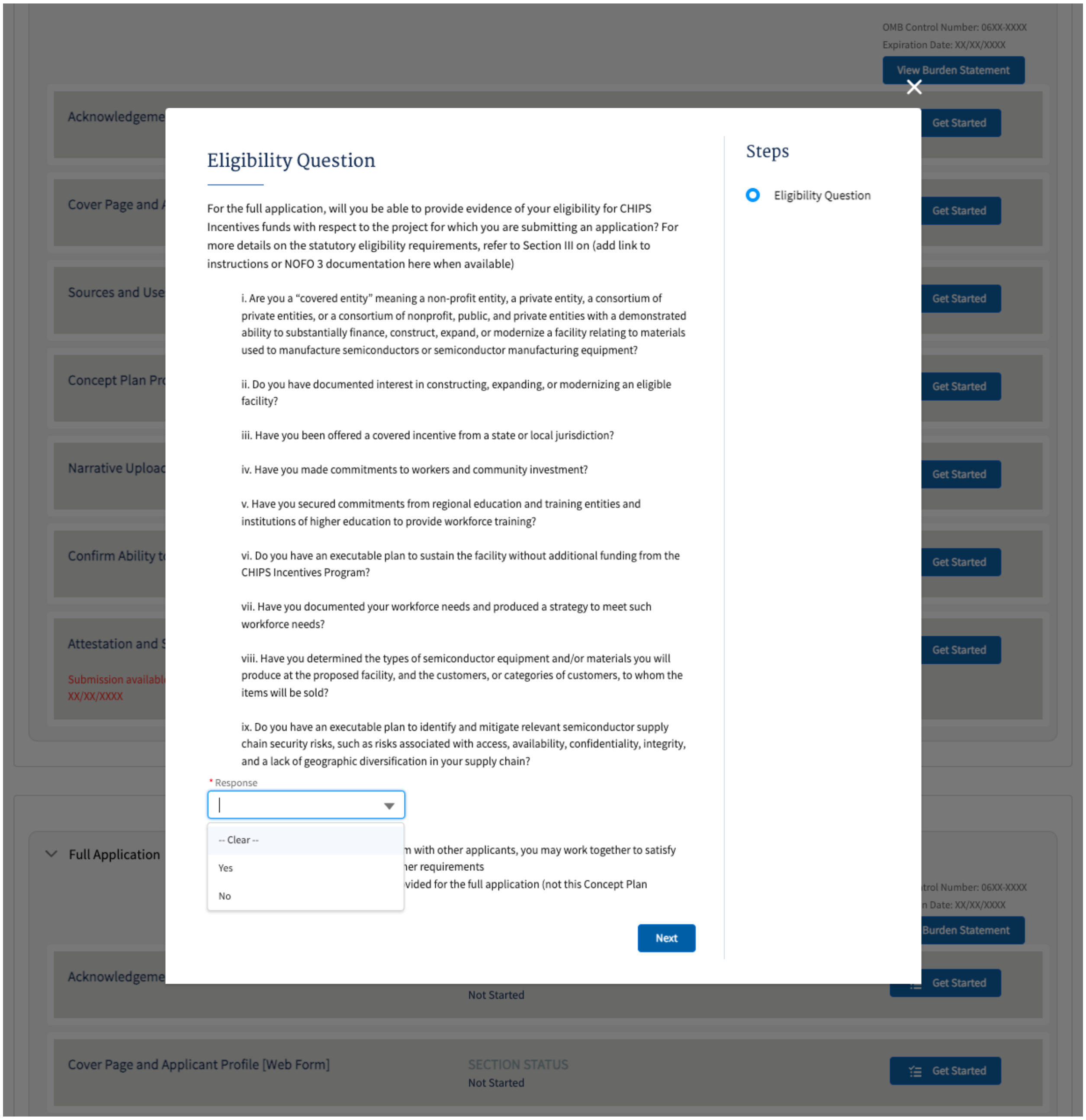
vii. Have you documented your workforce needs and produced a strategy to meet such workforce needs?

viii. Have you determined the types of semiconductor equipment and/or materials you will produce at the proposed facility, and the customers, or categories of customers, to whom the items will be sold?

ix. Do you have an executable plan to identify and mitigate relevant semiconductor supply chain security risks, such as risks associated with access, availability, confidentiality, integrity, and a lack of geographic diversification in your supply chain?

* Response

To note regarding documented interest:
- i. If applying as part of a consortium with other applicants, you may work together to satisfy various statutory eligibility and other requirements
- ii. These details will need to be provided for the full application (not this Concept Plan submission)



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* Response

-- Clear --
Yes
No

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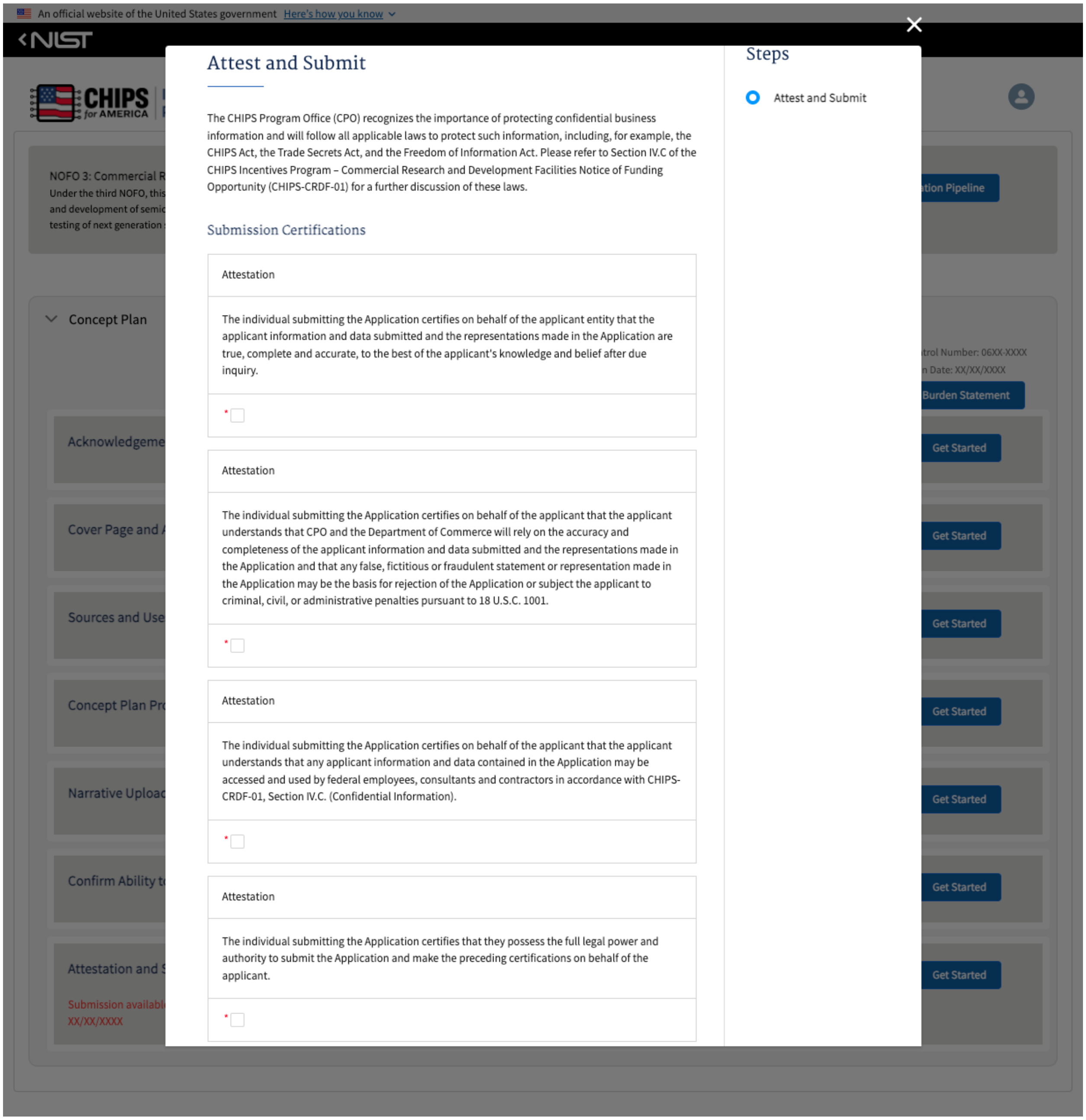
ner requirements
vided for the full application (not this Concept Plan

Picklist: Response

Picklist Values:

- Yes
- No

Attestation and Submission [Web Form]



Attest and Submit

The CHIPS Program Office (CPO) recognizes the importance of protecting confidential business information and will follow all applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to Section IV.C of the CHIPS Incentives Program – Commercial Research and Development Facilities Notice of Funding Opportunity (CHIPS-CRDF-01) for a further discussion of these laws.

Submission Certifications

Attestation

The individual submitting the Application certifies on behalf of the applicant entity that the applicant information and data submitted and the representations made in the Application are true, complete and accurate, to the best of the applicant's knowledge and belief after due inquiry.

* ☐

Attestation

The individual submitting the Application certifies on behalf of the applicant that the applicant understands that CPO and the Department of Commerce will rely on the accuracy and completeness of the applicant information and data submitted and the representations made in the Application and that any false, fictitious or fraudulent statement or representation made in the Application may be the basis for rejection of the Application or subject the applicant to criminal, civil, or administrative penalties pursuant to 18 U.S.C. 1001.

* ☐

Attestation

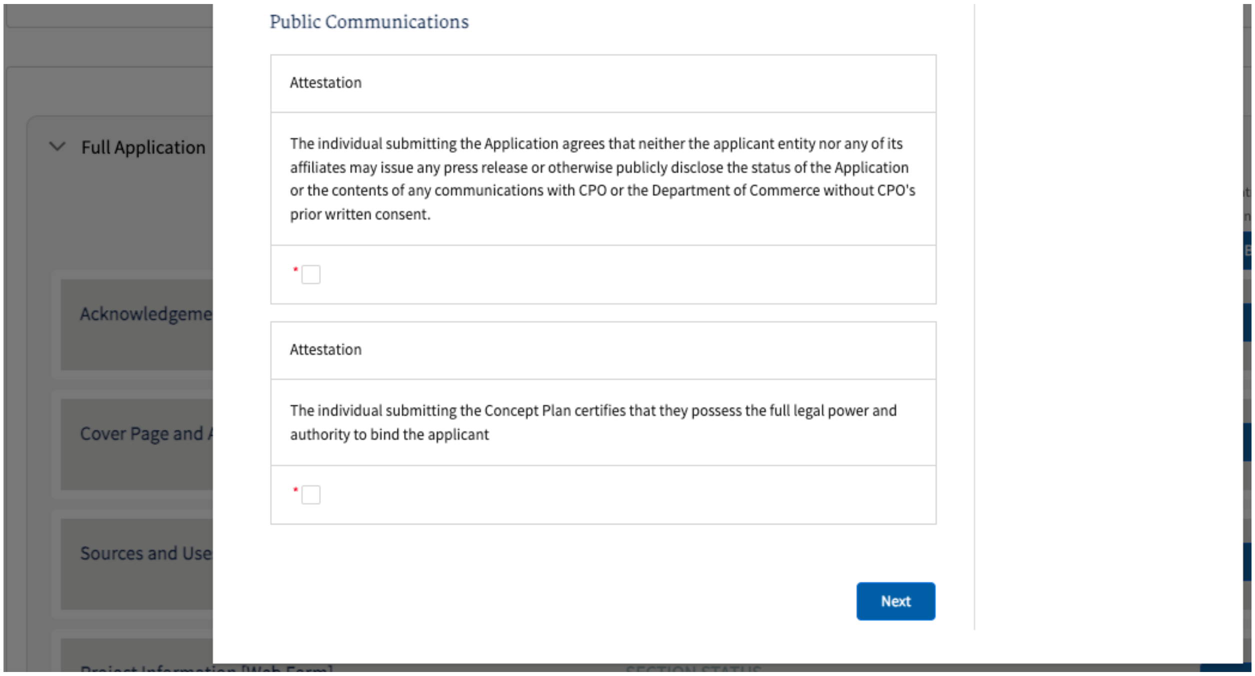
The individual submitting the Application certifies on behalf of the applicant that the applicant understands that any applicant information and data contained in the Application may be accessed and used by federal employees, consultants and contractors in accordance with CHIPS-CRDF-01, Section IV.C. (Confidential Information).

* ☐

Attestation

The individual submitting the Application certifies that they possess the full legal power and authority to submit the Application and make the preceding certifications on behalf of the applicant.

* ☐



Public Communications

Attestation

The individual submitting the Application agrees that neither the applicant entity nor any of its affiliates may issue any press release or otherwise publicly disclose the status of the Application or the contents of any communications with CPO or the Department of Commerce without CPO's prior written consent.

* ☐

Attestation

The individual submitting the Concept Plan certifies that they possess the full legal power and authority to bind the applicant

* ☐